

Surface ion traps for quantum computing

NPQI 2018

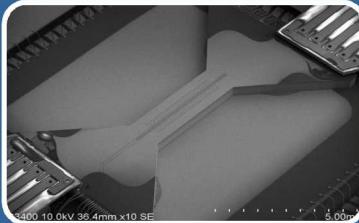


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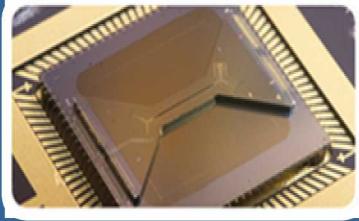
Daniel Stick, Sandia National Laboratories

*P. Maunz, M. G. Blain, D. Lobser, M. Revelle, C. Yale,
R. Haltli, C. Hogle, A. Hollowell*

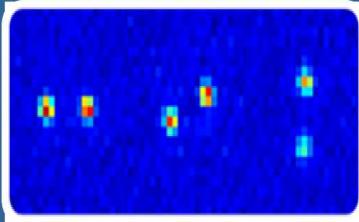
Outline



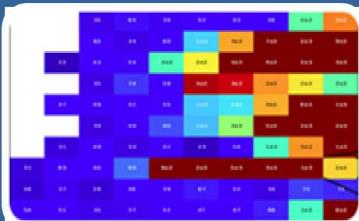
Trap fabrication, advantages and challenges



Recent trap types: High Optical Access trap & Microwave trap



Ion shuttling and swapping

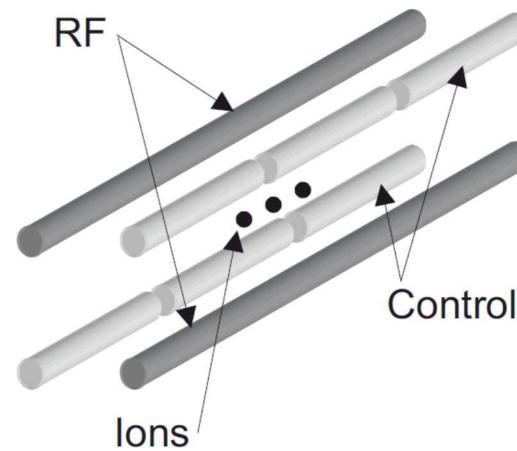


Characterization of quantum gates using Gate Set Tomography (GST)

Advantages/Challenges vs 3D

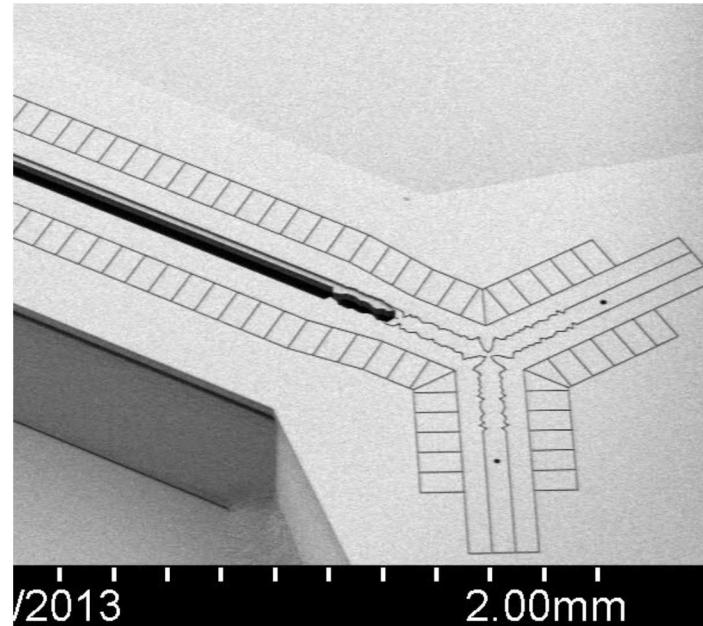
Advantages

- Greater field control (more electrodes)
- Flexible, precise 2D geometry
- More manufacturable
- Consistent geometry → consistent behavior
- Laser access
- Integration of other technologies (waveguides, detectors, filters...)



Challenges

- Lower depth (ion lifetime), anharmonicities in potential
- Proximity to surface (charging, heating)
- Delicate (dust, voltage)
- Capacitance
- Laser access



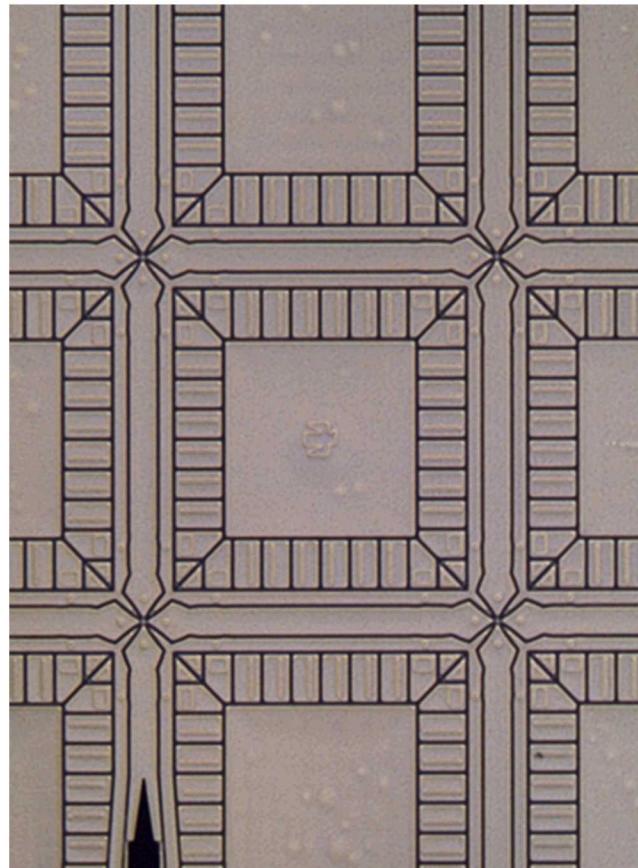
Capabilities & Requirements

Essential capabilities

- Reliable and consistent operation
- Store ions for long periods of time (hours)
- Move ions to achieve 2D connectivity
- Support high fidelity operations

MESA facility

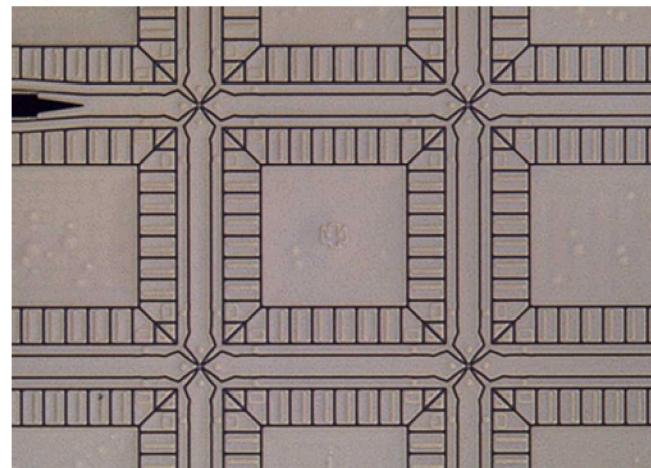
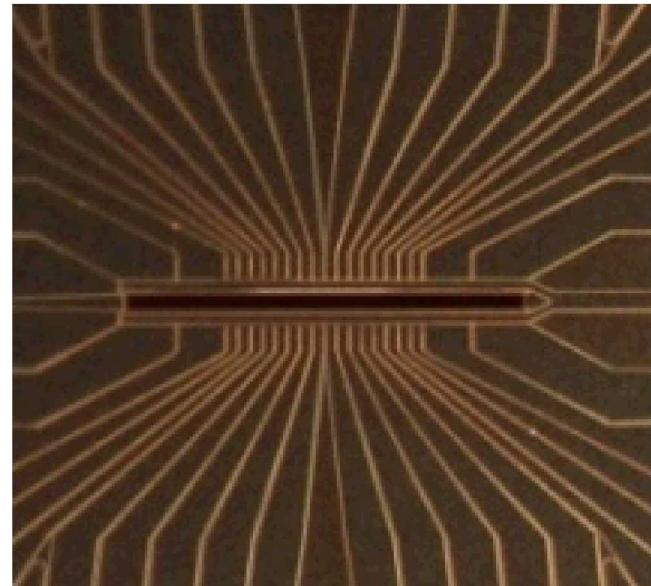
- Radiation hardened CMOS
- Leverages reliability of NW processing
- Large feature sizes (350 nm) match well with trap requirements



Capabilities & Requirements

Derived requirements

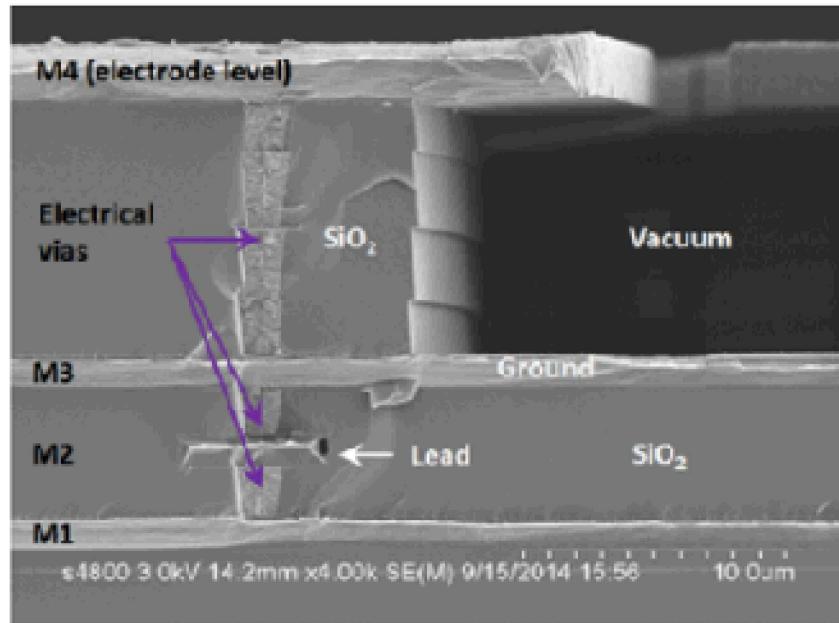
- Standardization (lithographically defined electrodes)
- Multi-unit production
 - ~90 devices per 6" wafer
- Multi-level lead routing for accessing interior electrodes
 - Connecting both control and RF electrodes
- Voltage breakdown >300 V @ ~ 50 MHz
- Overhung electrodes
- Low electric field noise (heating)
- Backside loading holes
- Trench capacitors
- High optical access (delivery and collection)



Capabilities & Requirements

Derived requirements

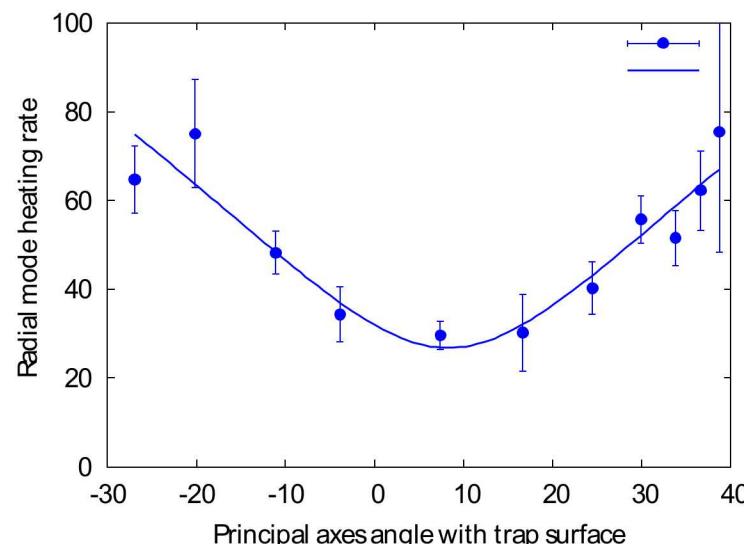
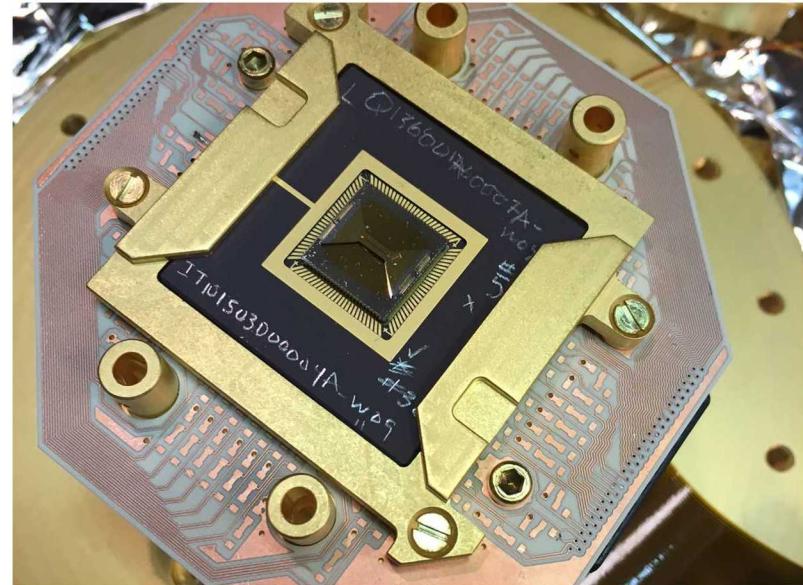
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- Backside loading holes
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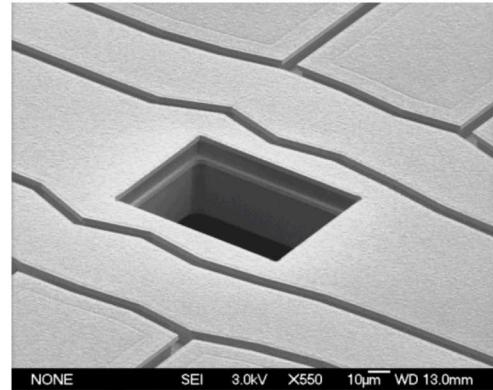


Capabilities & Requirements

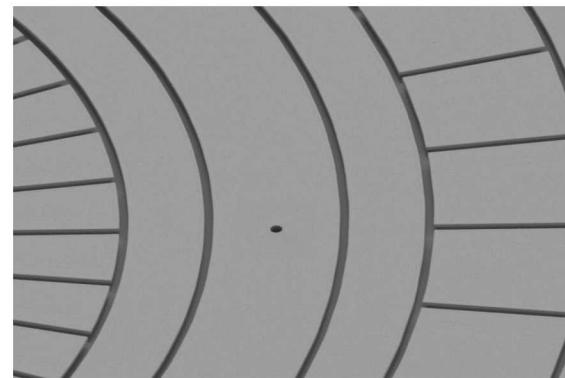
Derived requirements

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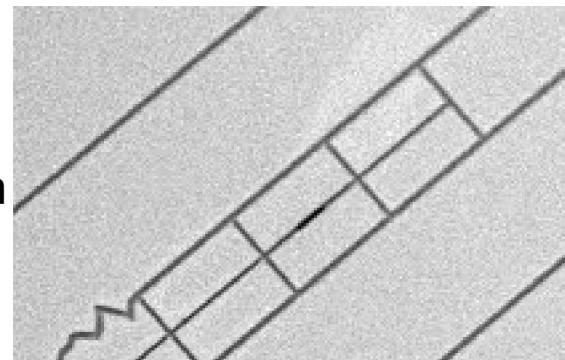
$50\mu\text{m} \times 80\mu\text{m}$
modulation
necessary



$10\mu\text{m}$ hole
still
perturbs
the field



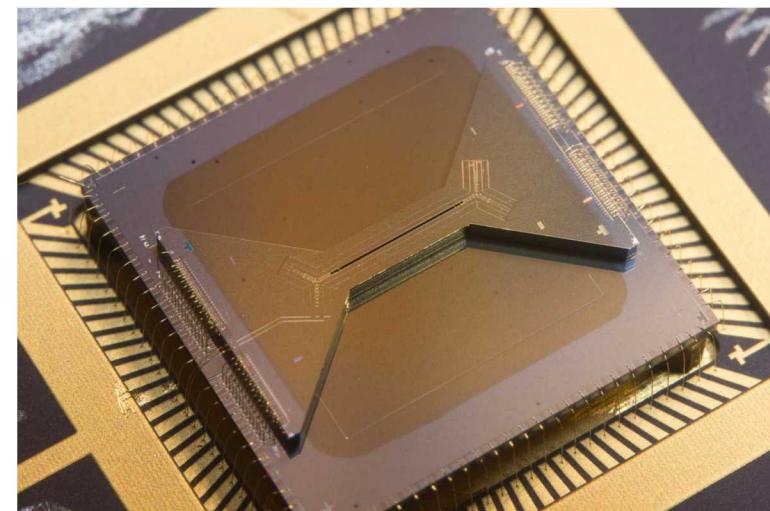
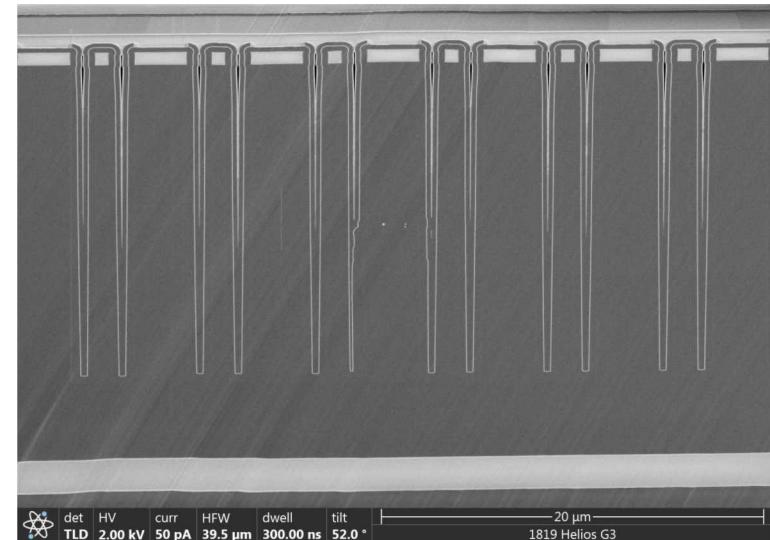
$3\mu\text{m} \times 20\mu\text{m}$



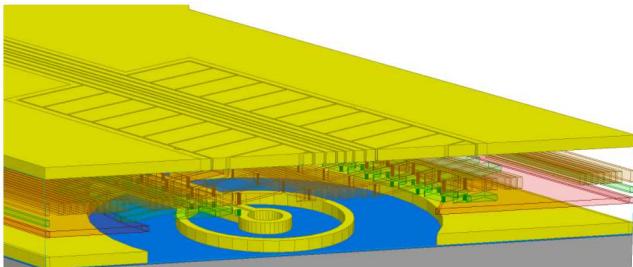
Capabilities & Requirements

Derived requirements

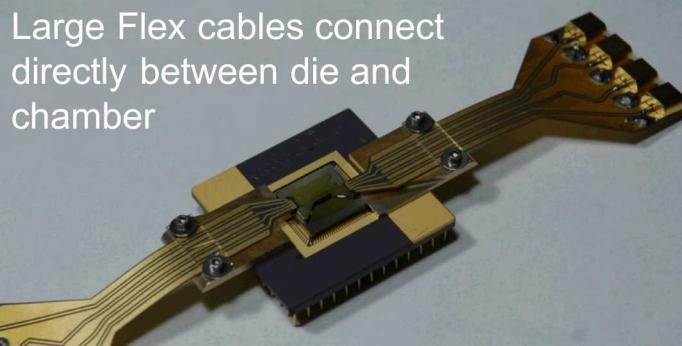
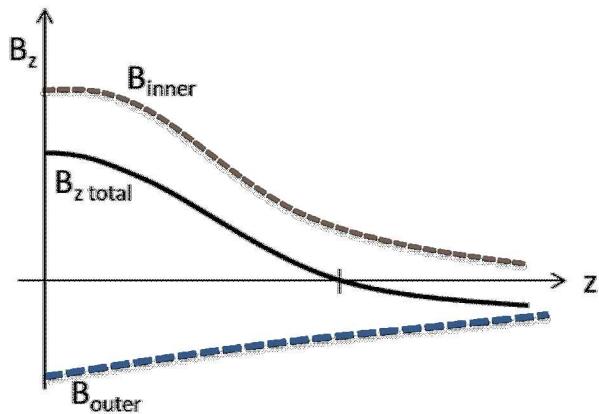
- Standardization (lithographically defined electrodes)
- Multi-unit production
- Multi-level lead routing for accessing interior electrodes
- Voltage breakdown >300 V @ ~ 50 MHz
- Overhung electrodes
- Low electric field noise (heating)
- Backside loading holes
- **Trench capacitors**
 - Current: 20V max, 1nF capacitance
 - Future: on-chip, 200 pF capacitance (but low inductance)
- High optical access (delivery and collection)



Microwave surface trap



Localized near-field microwaves



Advantages:

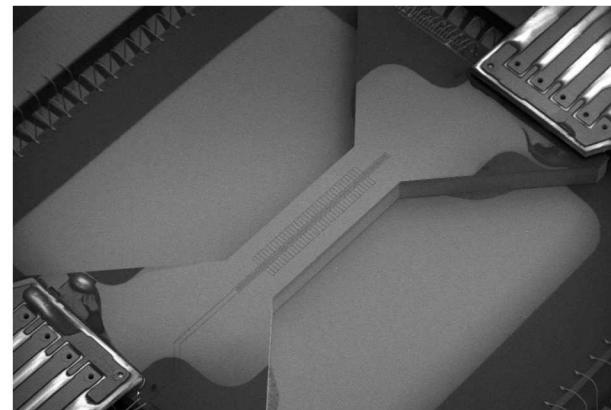
- Microwave radiation is easier to control & cheaper to implement
- Low power for Rabi oscillations
- Near field allows generation of microwave gradient fields

Challenges:

- Microwave delivery (12.6 GHz for Yb)
- Dissipation, heating, thermal management
- Generate both field and gradient

Field characteristics:

- x - and y - fields cancel along z -axis
- Generates uniform B_z and dB_z/dz with $B=0$
- Location of null determined by geometry & ratio of currents



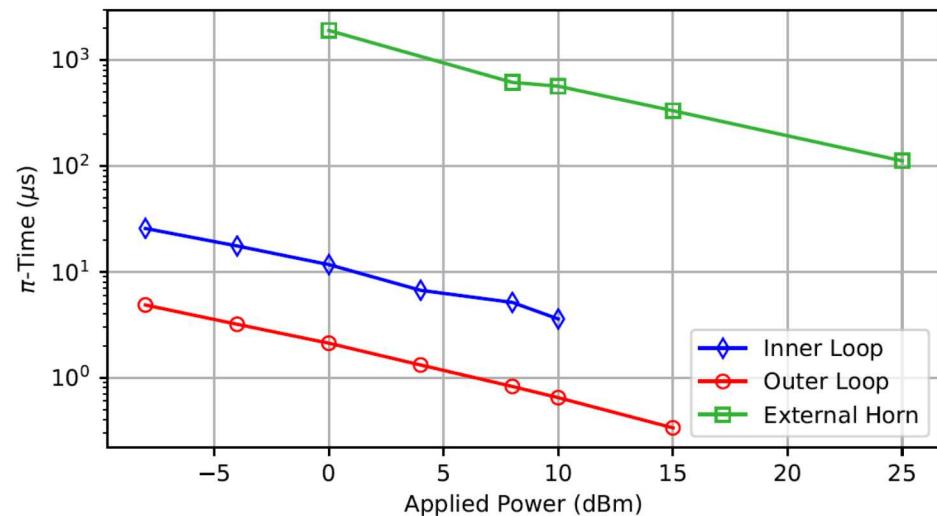
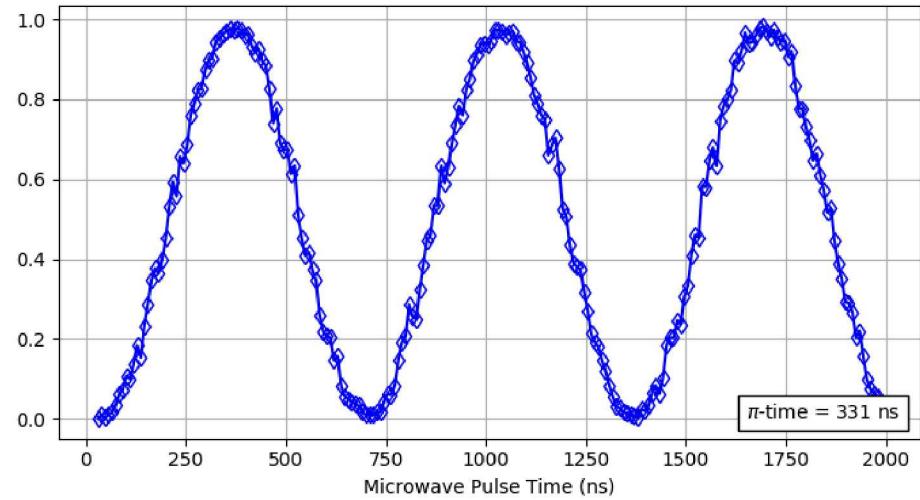
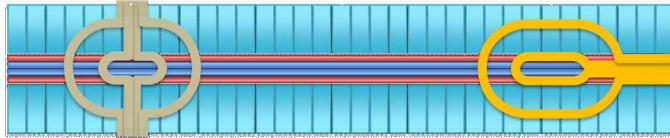
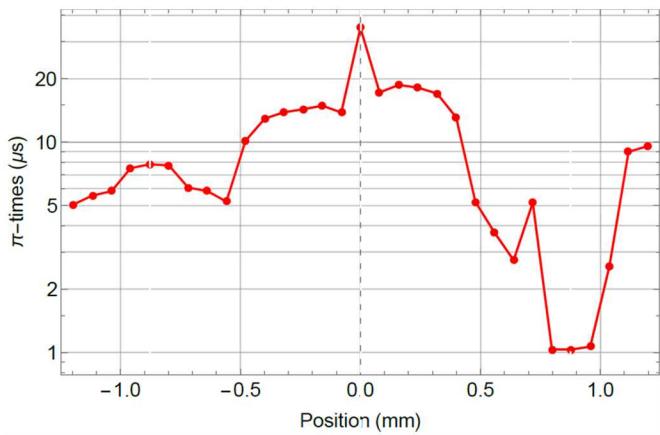
Microwave – single qubit

Fast, efficient Rabi flopping

- Losses between chamber and device ≈ 17 dB
- Realized fast Rabi flopping
330 ns with 15 dBm at chamber, -2 dBm at device

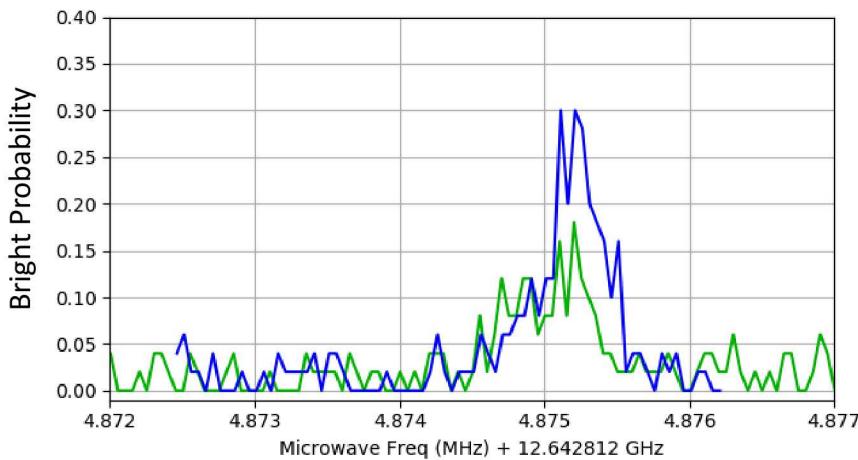
Localization

- Microwaves are localized at the loop
- Field suppressed factor 10
- Pickup from the second loop
- Field suppressed factor 5

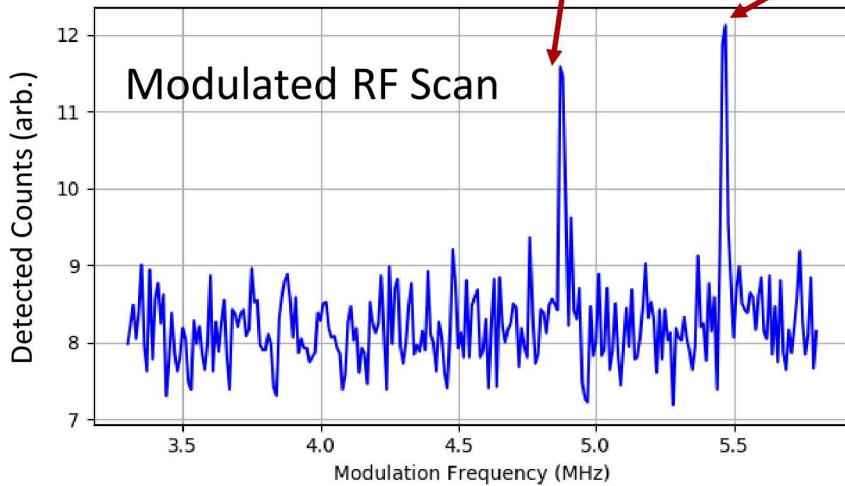
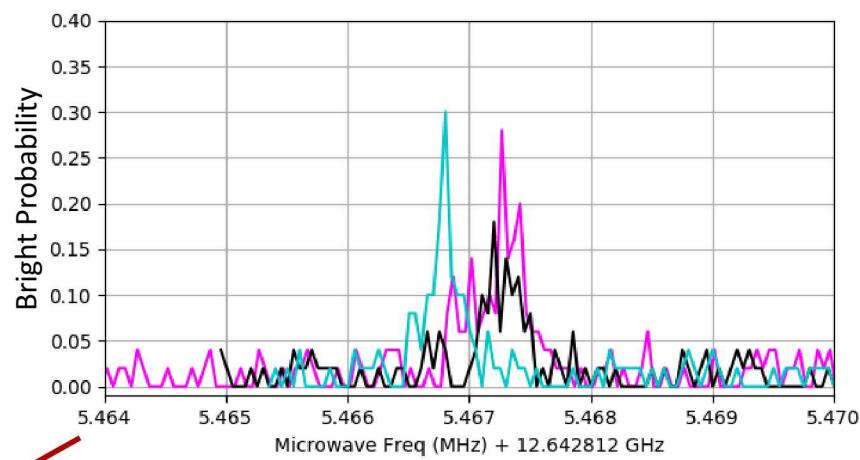


Microwave – motional control

Vertical Mode



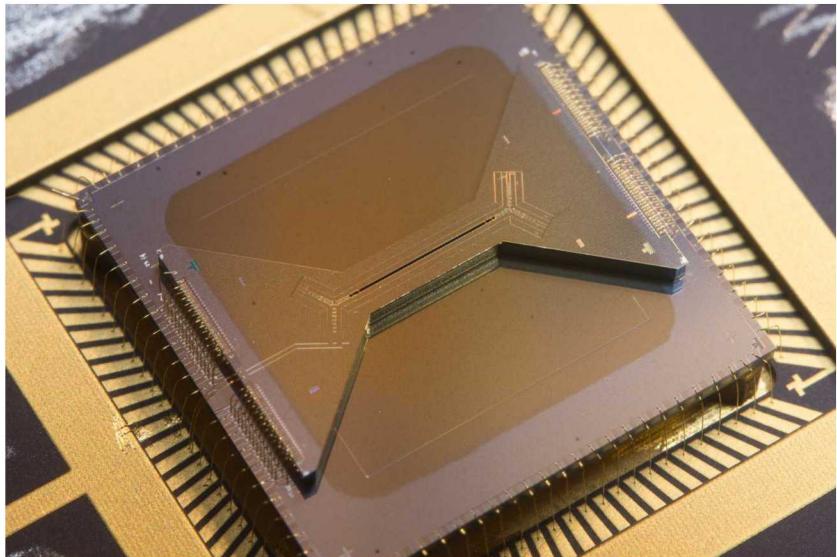
Horizontal Mode



Field characteristics:

- x- and y- fields cancel along z-axis
- Generates uniform B_z and dB_z/dz with $B=0$
- Location of null determined by geometry and ratio of currents
- Using <20 dBm on each loop
- Measurement time ~ 5 ms

High Optical Access (HOA)

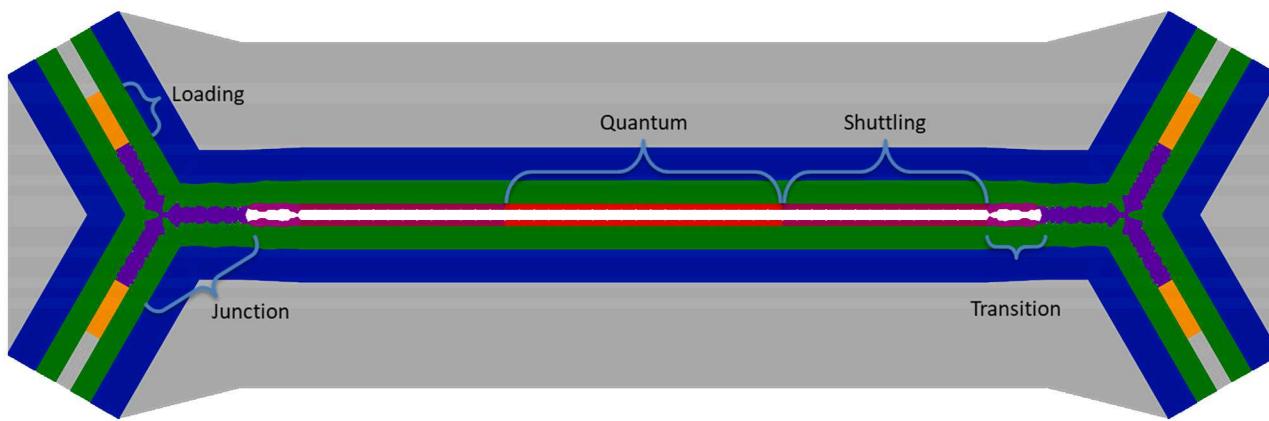


Optical access

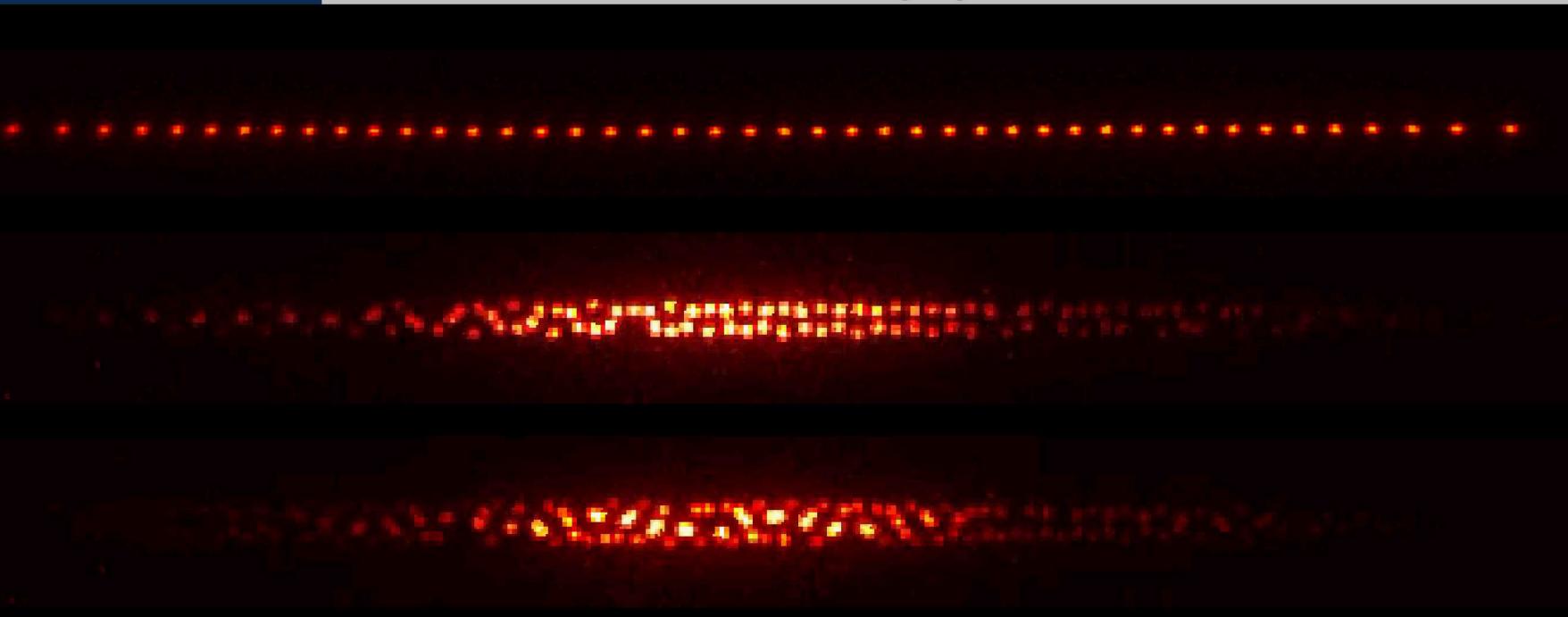
- Excellent optical access rivaling 3-D

Trap strength

- Radial trap frequency 2 - 5 MHz
- RF frequency 50 MHz
- Stable for long ion chains
- Low heating rates (30 q/s parallel to surface, 125 q/s perpendicular)
- >100 h observed
(while running measurements)
- >5 min without cooling

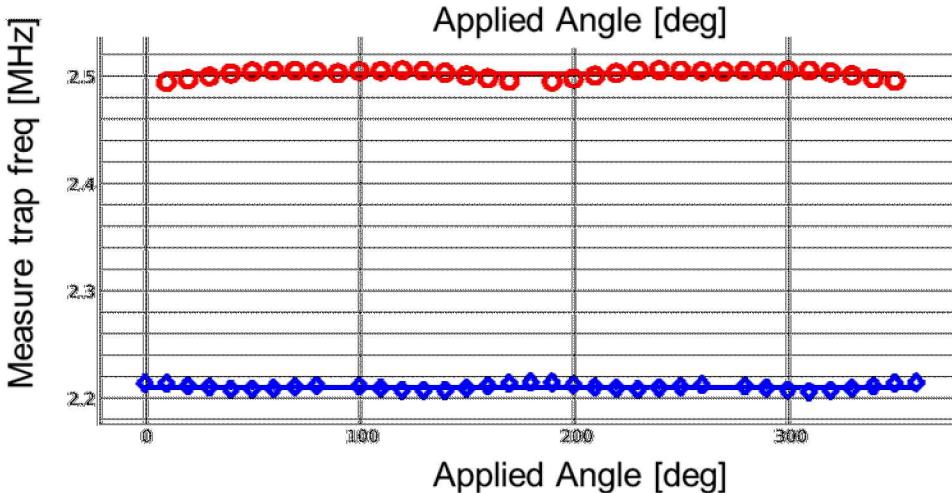
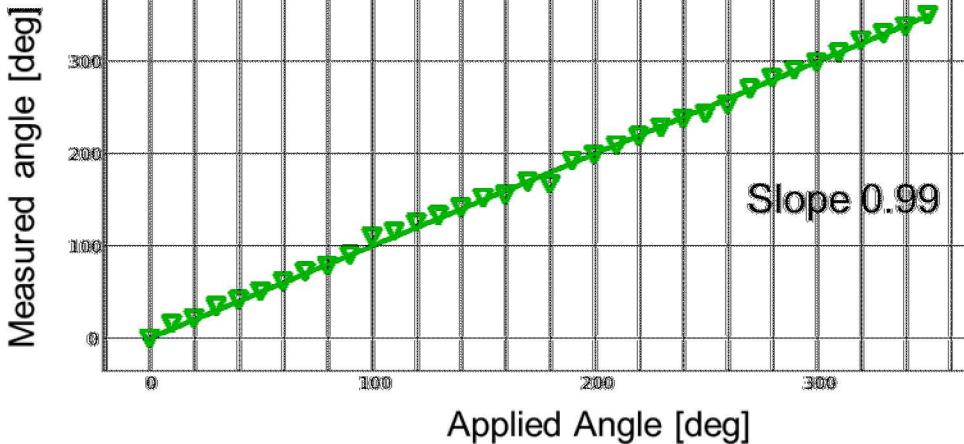


Trapped ion chains



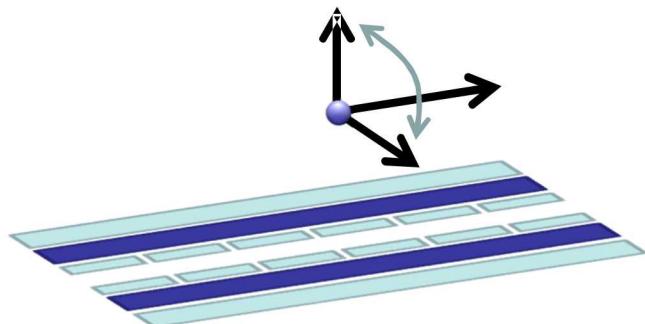
- Observed storage times between
 - 16 min for long linear chain
 - 16 h for 3d crystal
- Most likely limited by background collisions
- Property of vacuum conditions
- Losing all ions at once (one might come back)

HOA control



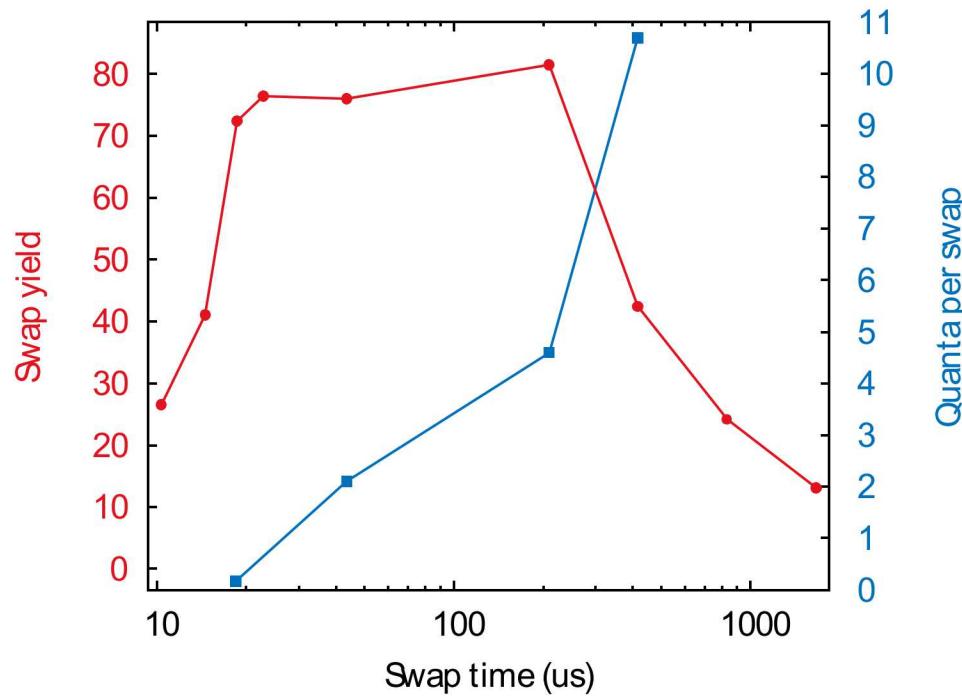
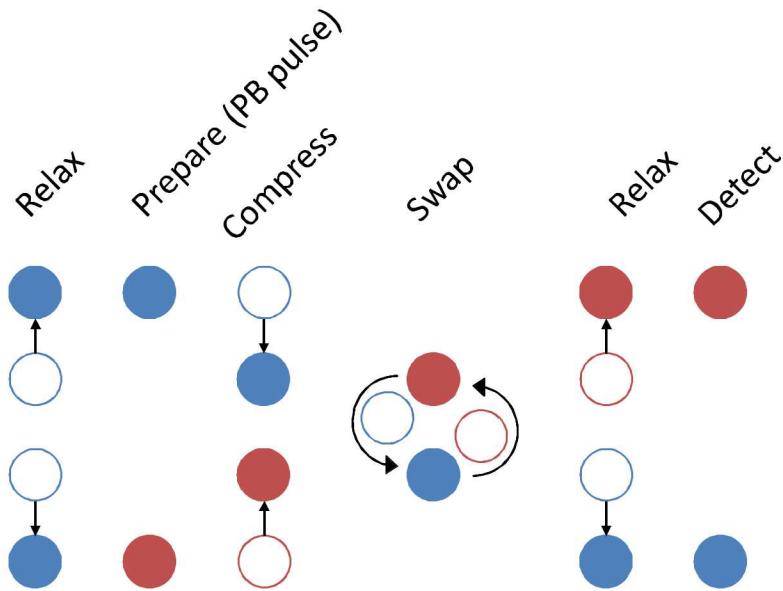
Electric field control

- Do we understand the trapping fields?
- Principal axes rotation realized as in simulation
- No change in trap frequencies
- The simulations accurately describe the fields and curvatures generated by the trap



Ion storage and transport

Swapping ions



Advantages of parametric trapping solutions:

- Primitives in terms of curvature tensor elements and can be applied at any location in the trap.
- Shuttling primitives can be easily combined
- Example: rotating ion crystal while translating through the trap

Diagnostics - single qubit gate

Gate Set Tomography (GST)

- No calibration required
- Detailed debug information
- Efficiently measures performance characterizing fault-tolerance (diamond norm)
- Amplifies errors
- Detects non-Markovian noise
- Robin Blume-Kohout, Erik Nielsen @ SNL

Desired “target” gates:

G_i Idle (Identity)

G_x $\pi/2$ rotation about x -axis

G_y $\pi/2$ rotation about y -axis

Fiducials:

$\{\}$

G_x

G_y

$G_x \cdot G_x$

$G_x \cdot G_x \cdot G_x$

$G_y \cdot G_y \cdot G_y$

Germs:

G_x

G_y

G_i

$G_x \cdot G_y$

$G_x \cdot G_y \cdot G_i$

$G_x \cdot G_i \cdot G_y$

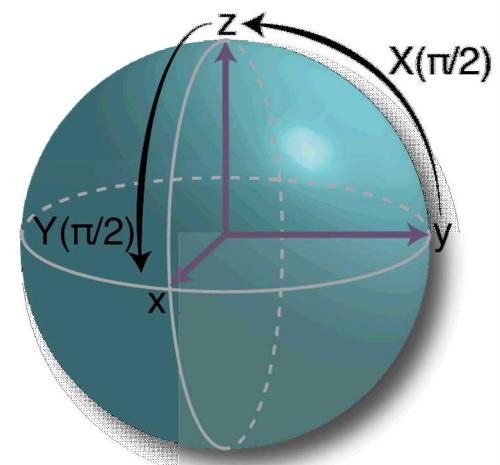
$G_x \cdot G_i \cdot G_i$

$G_y \cdot G_i \cdot G_i$

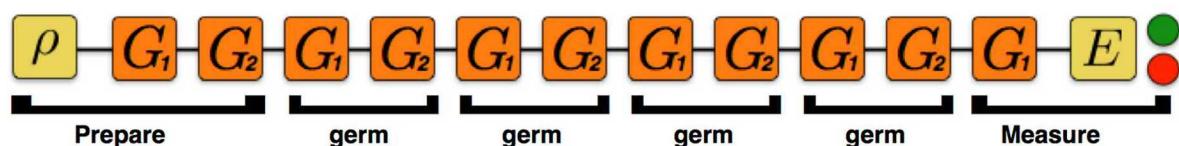
$G_x \cdot G_x \cdot G_i \cdot G_y$

$G_x \cdot G_y \cdot G_y \cdot G_i$

$G_x \cdot G_x \cdot G_y \cdot G_x \cdot G_y \cdot G_y$



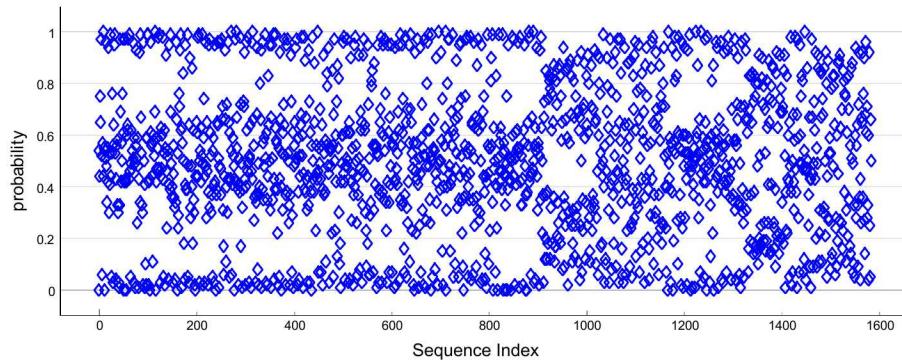
Single qubit BB1 compensated microwave gates on $^{171}\text{Yb}^+$



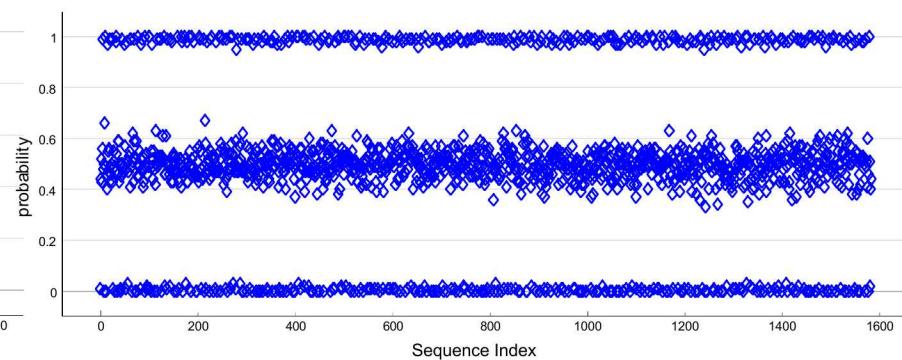
Diagnostics – single qubit gate

GST – Microwaves (horn)

Raw data poor gates

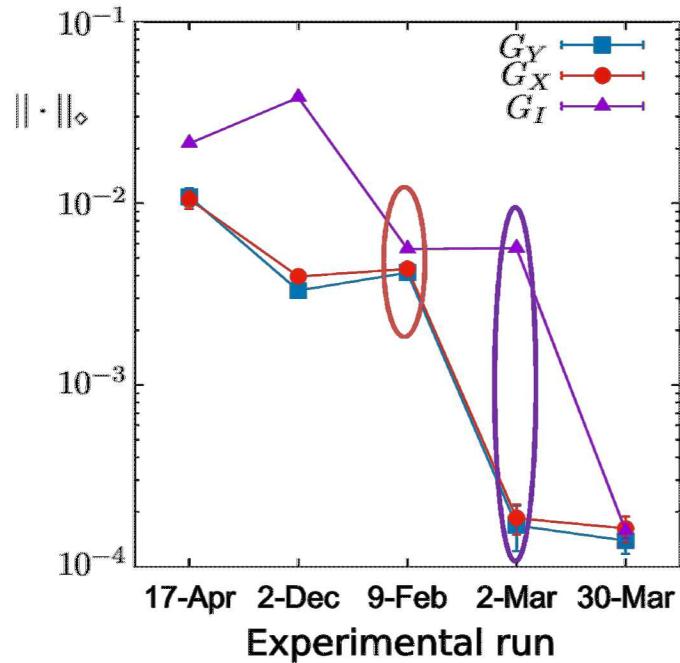


Raw data good gates



Gate	Rotn. axis	Angle
G_I	0.5252	
	-0.009	
	0.8506	
	-0.0244	0.001699π
G_X	-3×10^{-6}	
	-1	
	-3×10^{-5}	0.501308π
	-0.009	
G_Y	-0.2474	
	0.0001	
	0.9689	
	-0.0001	0.501366π

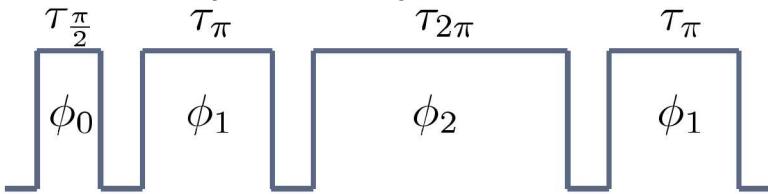
Gate	Rotn. axis	Angle
G_I	-0.0035	
	0.014	
	-0.9999	
	0.0006	0.001769π
G_X	-3×10^{-5}	
	-1	
	1×10^{-4}	0.500007π
	0.0006	
G_Y	0.1104	
	4×10^{-5}	
	0.9939	
	0.0005	0.50001π



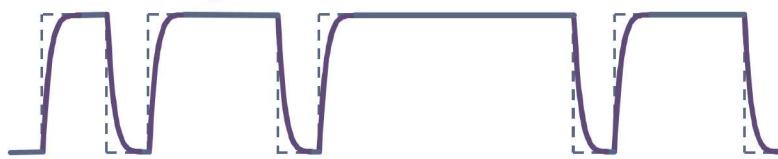
GST – Microwaves (horn)

1. Fix switching artifacts

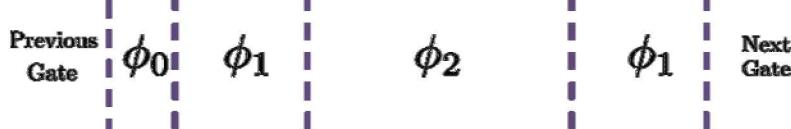
BB1 compensated pulse



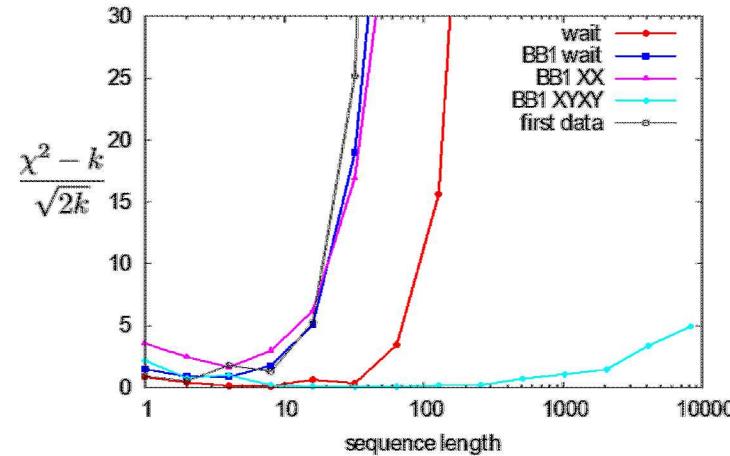
Switching artifacts



- Calibrate gap offset
- Discontinuous phase updates are used in place of gaps. Solves issues related to finite turn-on time and allows for continuous feedback on the driving field power.



2. BB1 sequence for identity gate



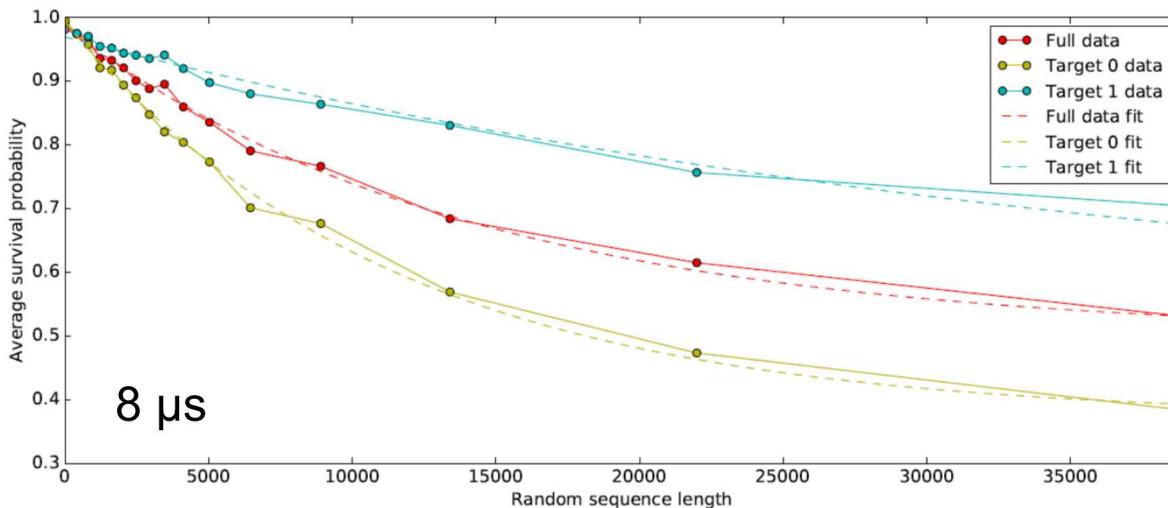
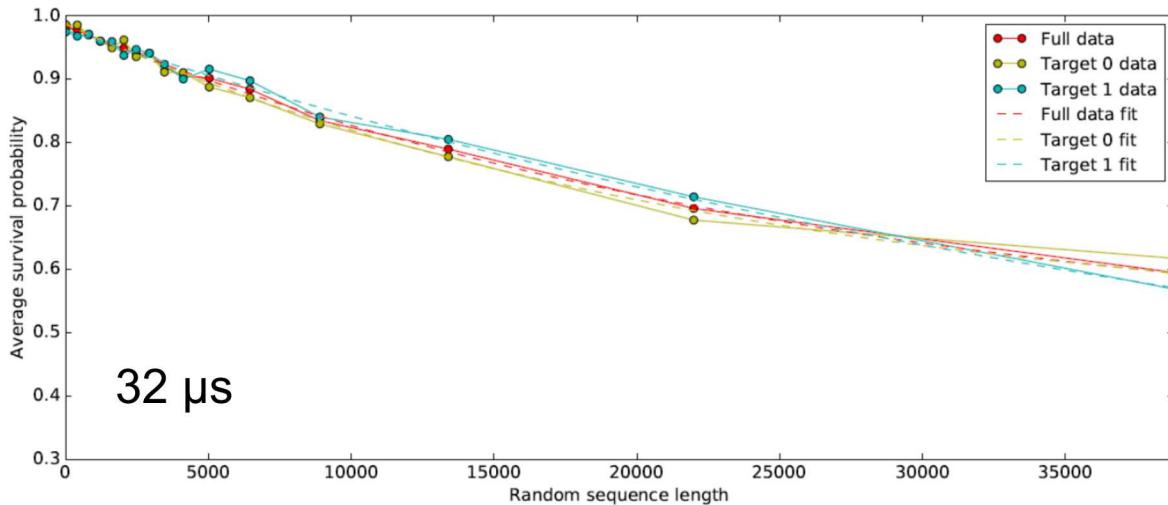
- BB1 decoupled microwave gates with decoupled identity have very small non-Markovian noise
- Decoupling sequence for identity gate
- Drift control for π -time and qubit frequency

Gate	Process Infidelity	$1/2 \diamond$ -Norm
G_I	$6.9(6) \times 10^{-5}$	$7.9(7) \times 10^{-5}$
G_X	$6.1(7) \times 10^{-5}$	$7.0(15) \times 10^{-5}$
G_Y	$7.2(7) \times 10^{-5}$	$8.1(15) \times 10^{-5}$

95% confidence intervals

Diagnostics – single qubit gate GST – Microwaves (on-chip)

- Off-resonant coupling observed with long RB sequences targeting both qubit states
- Culprit – impurity in polarizations that lead to leakage into the Zeeman states



Diagnostics – single qubit gate

Laser based Raman gates



co-propagating beam geometry

- Motion independent
- No optical phase imprinted

- BB1 dynamically compensated pulse sequences

GST results:

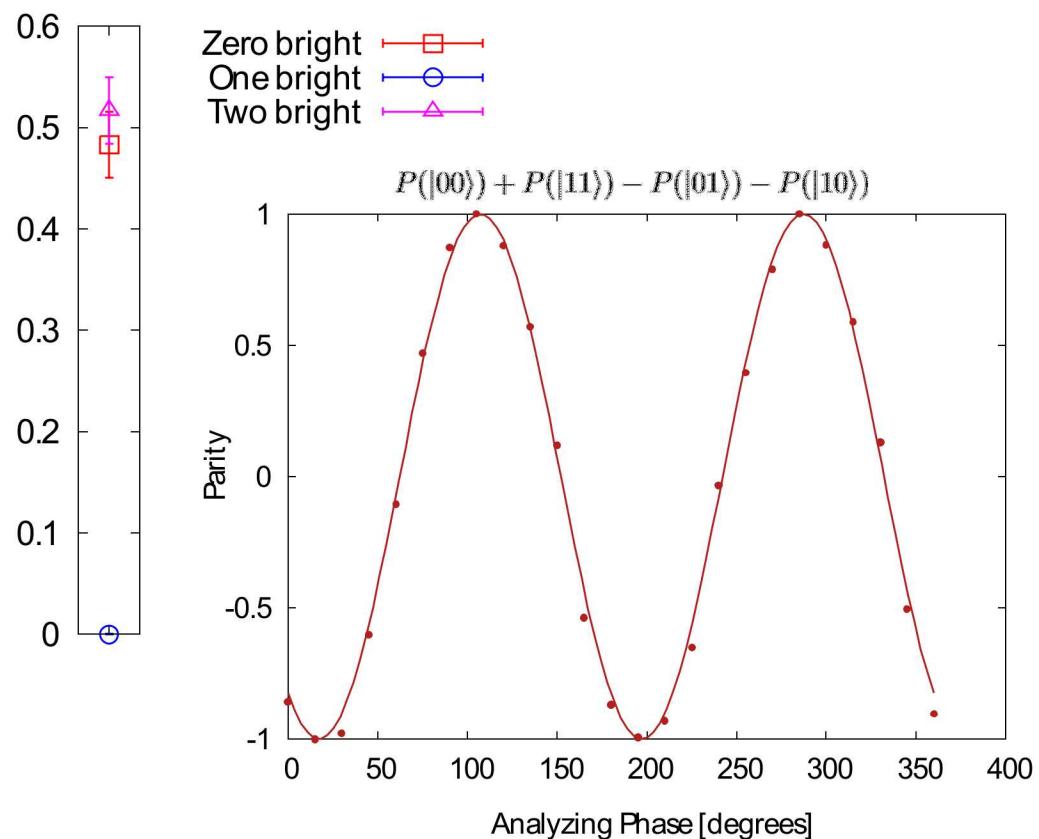
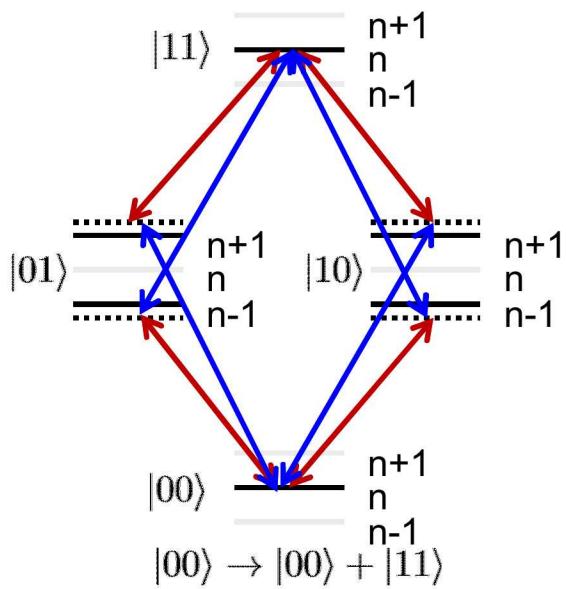
95% confidence intervals

	Conventional pulses		Gapless pulses	
Gate	Process Infidelity	$1/2 \diamond$ -Norm	Process Infidelity	$1/2 \diamond$ -Norm
G_I	$0.05(2) \times 10^{-4}$	$12(1) \times 10^{-4}$	$1.1(1) \times 10^{-4}$	$5.3(2) \times 10^{-4}$
G_X	$1.3(1) \times 10^{-4}$	$4(2) \times 10^{-4}$	$0.5(1) \times 10^{-4}$	$2(6) \times 10^{-4}$
G_Y	$1.6(4) \times 10^{-4}$	$4(3) \times 10^{-4}$	$0.7(1) \times 10^{-4}$	$4(9) \times 10^{-4}$

Process infidelity and $1/2 \diamond$ -Norm
values for BB1

Mølmer-Sørensen gates

- Mølmer-Sørensen gates [1]
- All two-qubit gates implemented using Walsh compensation pulses [2]

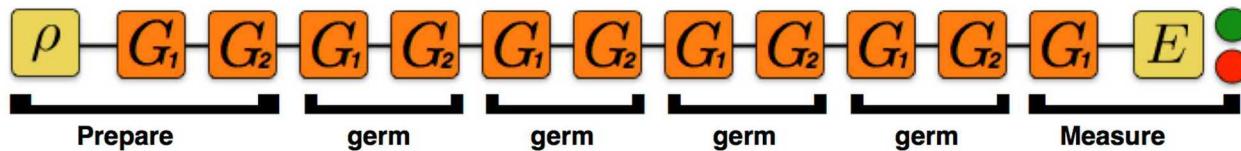


$$\mathcal{F} = \frac{1}{2}(P(|00\rangle) + P(|11\rangle)) + \frac{1}{4}c \approx 0.995$$

[1] K. Mølmer, A. Sørensen, PRL 82, 1835 (1999)

[2] D. Hayes et al. Phys. Rev. Lett. 109, 020503 (2012)

GST on symmetric subspace



Basic gates: G_I

$$G_{XX} = G_X \otimes G_X$$

$$G_{YY} = G_Y \otimes G_Y$$

$$G_{MS}$$

Preparation Fiducials:

$$\{\}$$

$$G_{XX}$$

$$G_{YY}$$

$$G_{MS}$$

$$G_{XX}G_{MS}$$

$$G_{YY}G_{MS}$$

Germs:

$$G_I$$

$$G_{XX}$$

$$G_{YY}$$

$$G_{MS}$$

$$G_I G_{XX}$$

$$G_I G_{YY}$$

$$G_I G_{MS}$$

$$G_{XX} G_{YY}$$

$$G_{XX} G_{MS}$$

$$G_{YY} G_{MS}$$

$$G_I G_I G_{XX}$$

$$G_I G_I G_{YY}$$

Detection Fiducials:

$$\{\}$$

$$G_{XX}$$

$$G_{YY}$$

$$G_{MS}$$

$$G_{XX} G_{MS}$$

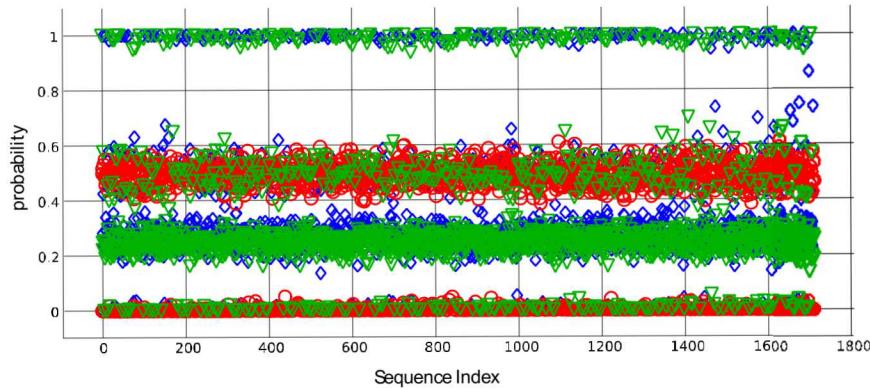
$$G_{YY} G_{MS}$$

$$G_{XX}^3$$

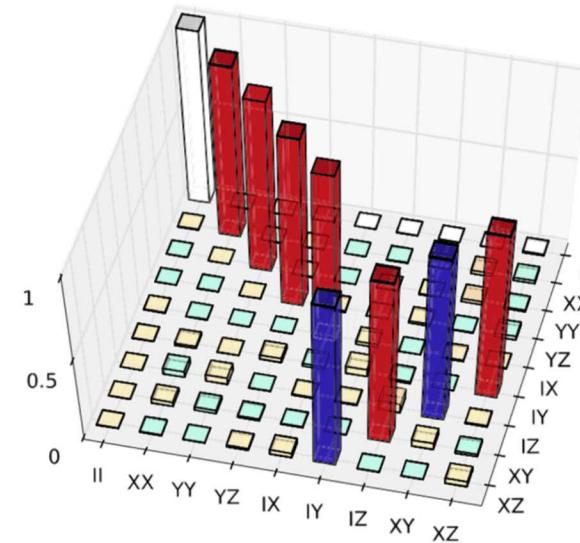
$$G_{YY}^3$$

$$G_{YY}^2 G_{MS}$$

GST on symmetric subspace



Zero ions bright
 One ion bright
 Two ions bright



Gate	Process infidelity	$\frac{1}{2}$ Diamond norm
G_I	$1.6 \times 10^{-3} \pm 1.6 \times 10^{-3}$	$28 \times 10^{-3} \pm 7 \times 10^{-3}$
G_{XX}	$0.4 \times 10^{-3} \pm 1.0 \times 10^{-3}$	$27 \times 10^{-3} \pm 5 \times 10^{-3}$
G_{YY}	$0.1 \times 10^{-3} \pm 0.9 \times 10^{-3}$	$26 \times 10^{-3} \pm 4 \times 10^{-3}$
G_{MS}	$4.2 \times 10^{-3} \pm 0.6 \times 10^{-3}$	$38 \times 10^{-3} \pm 5 \times 10^{-3}$

95% confidence intervals

Process fidelity of two-qubit Mølmer-Sørensen gate > 99.5%

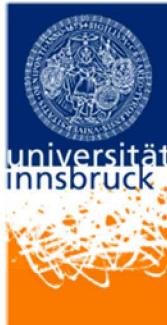
Summary

Leveraging DOE facilities

- MESA facility – capabilities align well with trap requirements
 - Engineers and technologists essential to fabricating and packaging the many traps needed at SNL and academic/commercial partners
- Engineering and simulations
 - Microwave design
 - Quantum theory – tomography and error correction
- LDRD support (primary support from IARPA)

Future research

- Ion transport to support logical qubit operations
- Continue to improve fidelity in context of logical qubits



Postdoc positions available

Trap design and fabrication

Matthew Blain

Ed Heller

Corrie Herrmann

Becky Loviza

John Rembetski

Paul Resnick

SiFab team

Trap packaging

Ray Haltli

Drew Hollowell

Anathea Ortega

Tipp Soumphonphakdy

GST protocols

Robin Blume-Kohout

Kenneth Rudinger

Eric Nielsen

Trap design and testing

Peter Maunz

Craig Hogle

Daniel Lobser

Melissa Revelle

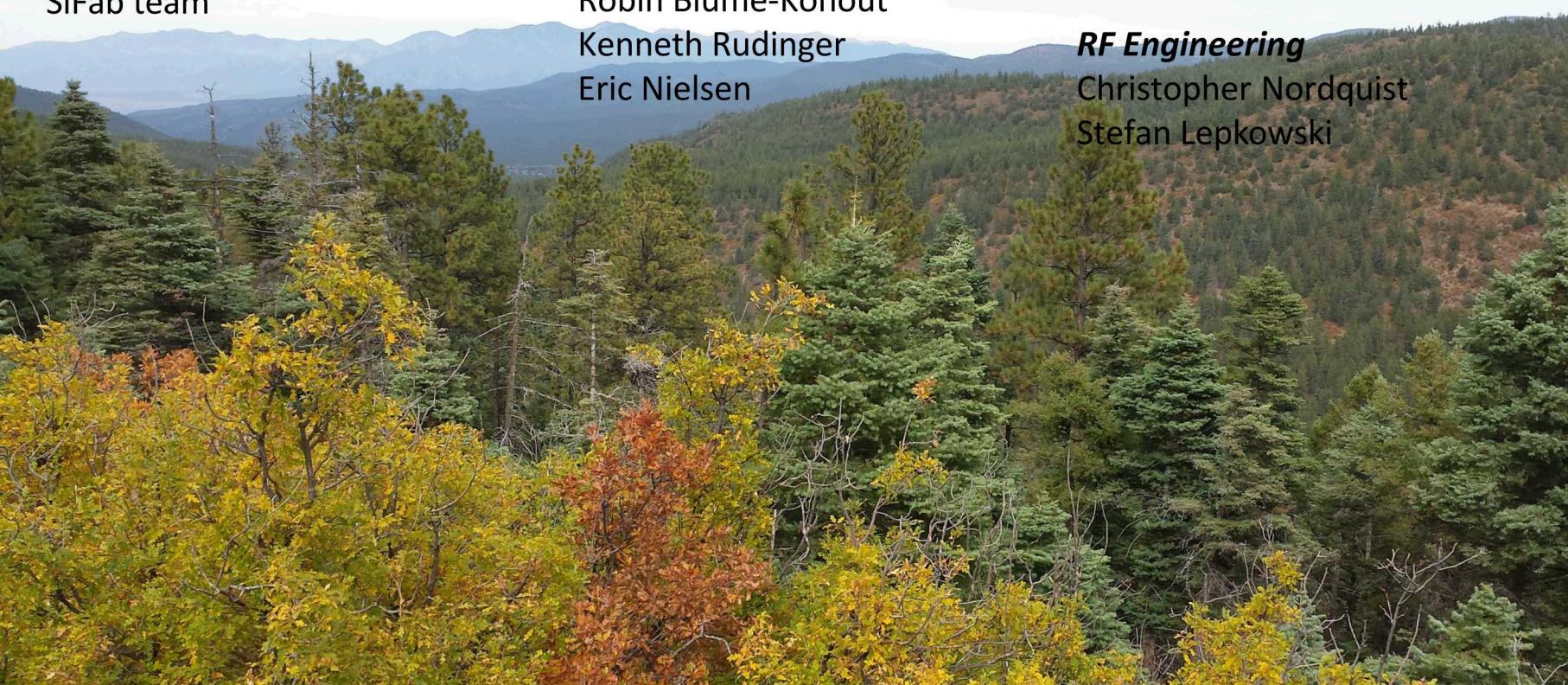
Dan Stick

Christopher Yale

RF Engineering

Christopher Nordquist

Stefan Lepkowski



Backup slides

Microwave error sources

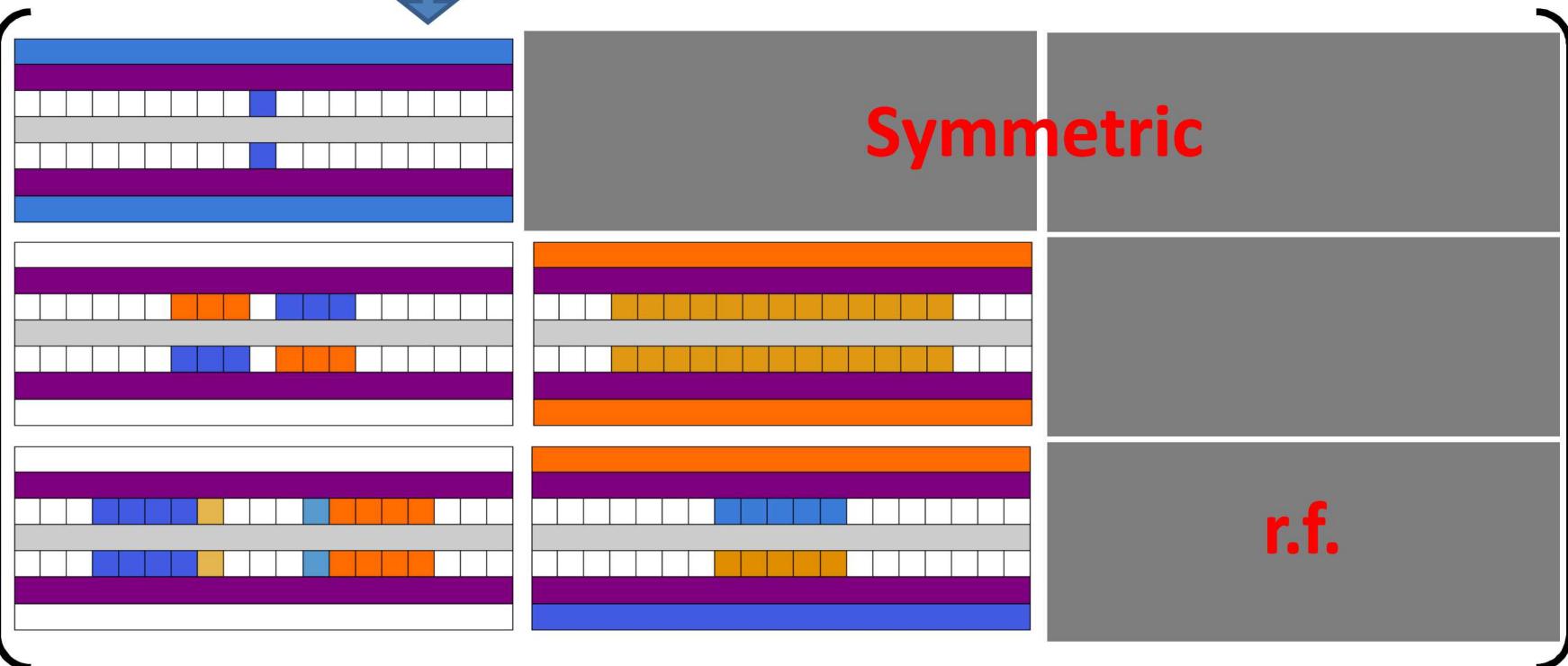
- Time resolution:
 - Current time resolution is 5 ns
 - π -times are 45 μ s
 - ratio: 10^{-4}
 - Possible due to broadband pulses
- Coherence time:
 - $T_2^* = 1$ s
 - longest pulse sequences 8192 : 1.66 s

Transport

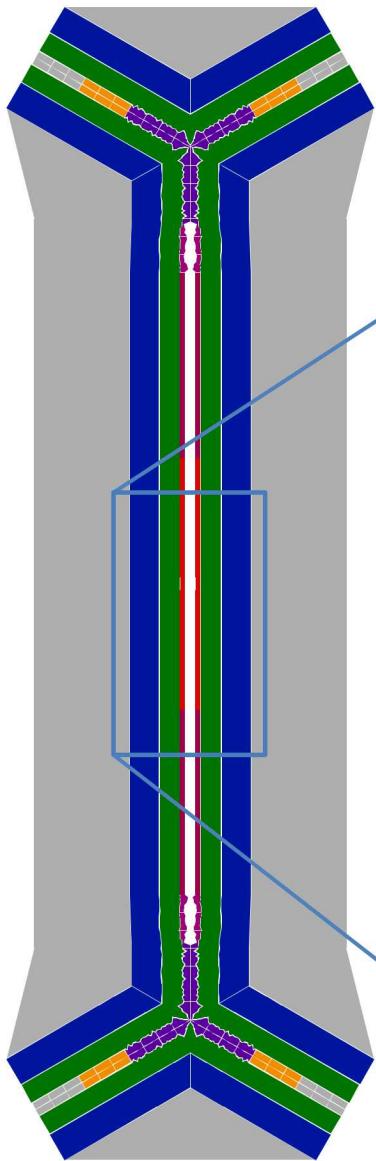
$$\mathcal{H} = \begin{pmatrix} \frac{\partial \phi}{\partial x \partial x} & \frac{\partial \phi}{\partial x \partial y} & \frac{\partial \phi}{\partial x \partial z} \\ \frac{\partial \phi}{\partial y \partial x} & \frac{\partial \phi}{\partial y \partial y} & \frac{\partial \phi}{\partial y \partial z} \\ \frac{\partial \phi}{\partial z \partial x} & \frac{\partial \phi}{\partial z \partial y} & \frac{\partial \phi}{\partial z \partial z} \end{pmatrix}$$

↓

- Symmetric curvature tensor
- 6 degrees of freedom
- Determines trap frequencies and principal axes rotations
- Traceless for static fields
- Trace is generated by rf pseudopotential

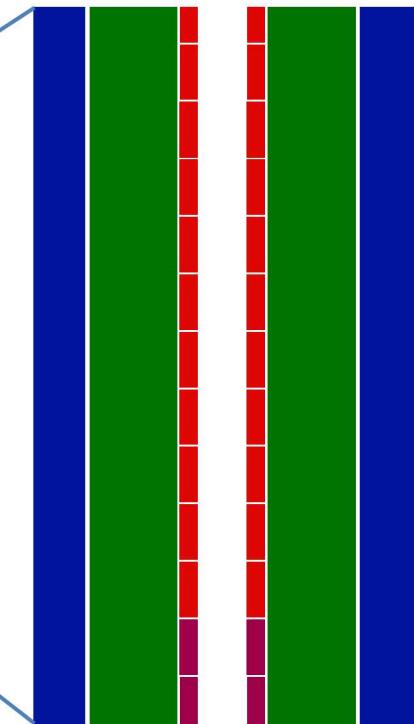


Voltage application

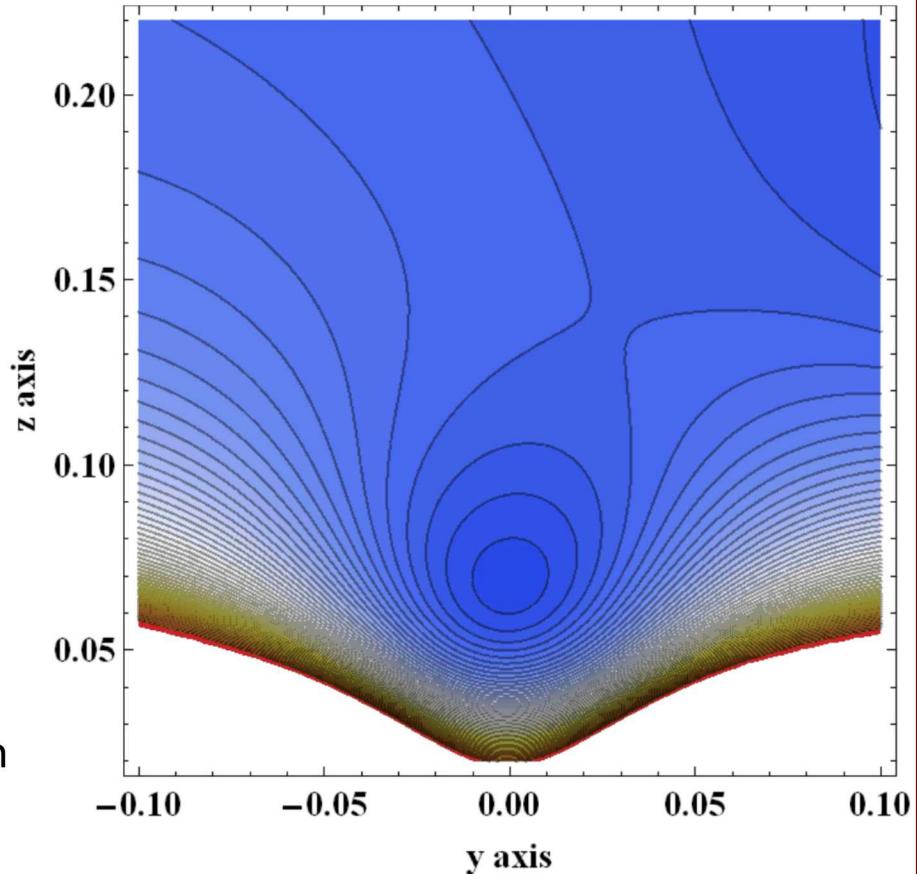


Trapping potential

- Axial frequency: 500 kHz [<5 V]
- Radial frequency: 2.8 MHz, 3.1 MHz [250 Vrf @ 40 MHz]

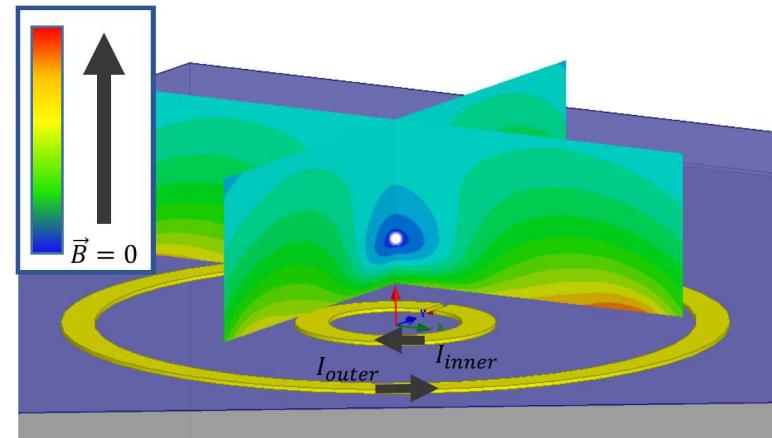
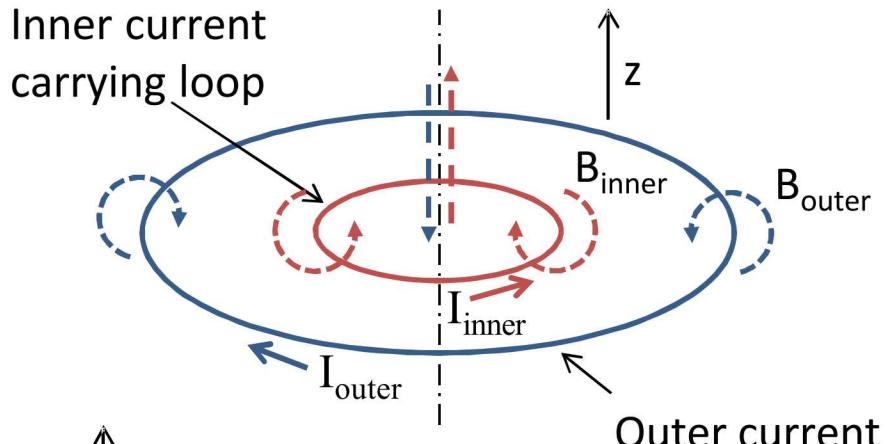


- 70 μ m electrode pitch
- 70 μ m ion height



Microwave surface trap

“Ideal” Two-Loop Design



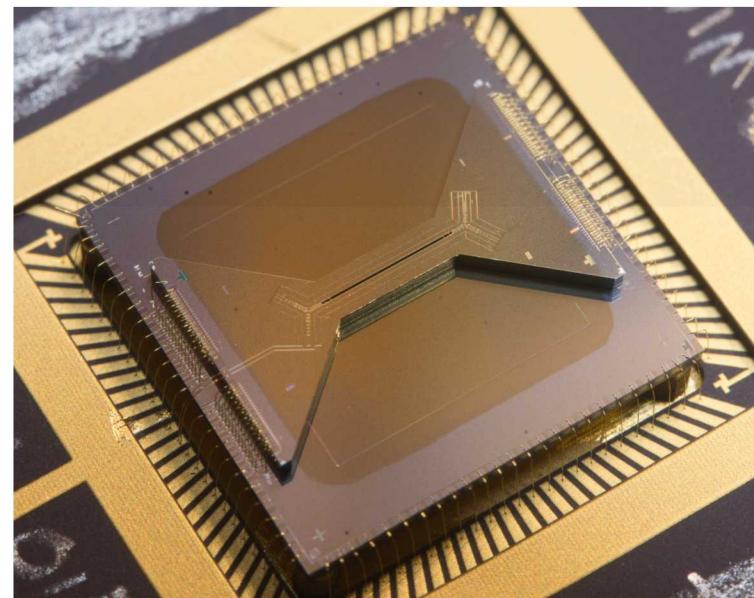
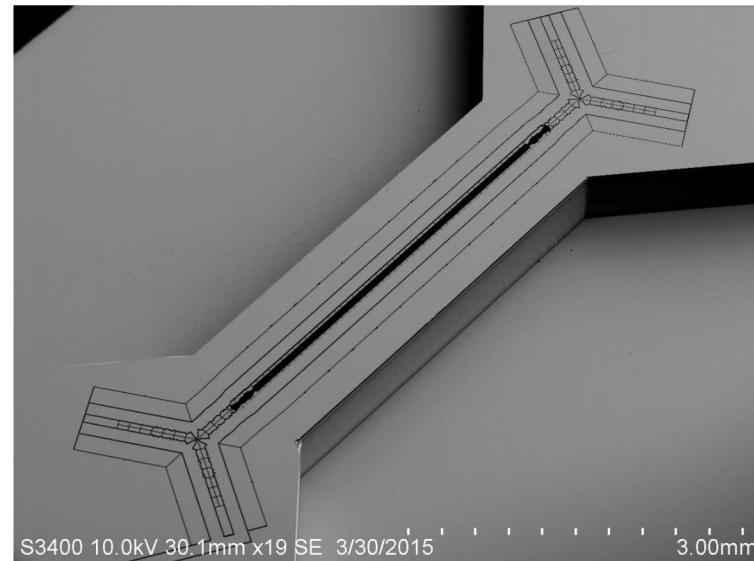
- x- and y- fields cancel along z-axis
- Generates uniform B_z and dB_z/dz with $B=0$
- Location of null determined by geometry and ratio of currents

Two-loop concept developed at Sandia in 2012 (SAND2015-9513)

(C. Highstrete, S. M. Scott, J. D. Sterk, C. D. Nordquist, J. E. Stevens, C. P. Tigges, M. G. Blain)

Trap fabrication capability

- Any geometry can be realized
 - Islanded electrodes
 - Clusters of small electrodes
 - Segmented electrodes close to trapping location
- Any (reasonable) shape can be realized
Example: Bowtie shape for increased numerical aperture
 - $4\mu\text{m}$ focus possible (@ 370nm)
 - Numerical Aperture 0.1
- Electrodes on different metal levels are possible
- Enables scalability (Quantum-CCD)
- Uses capabilities exceeding CMOS-7 (remove dielectrics, trap shape)



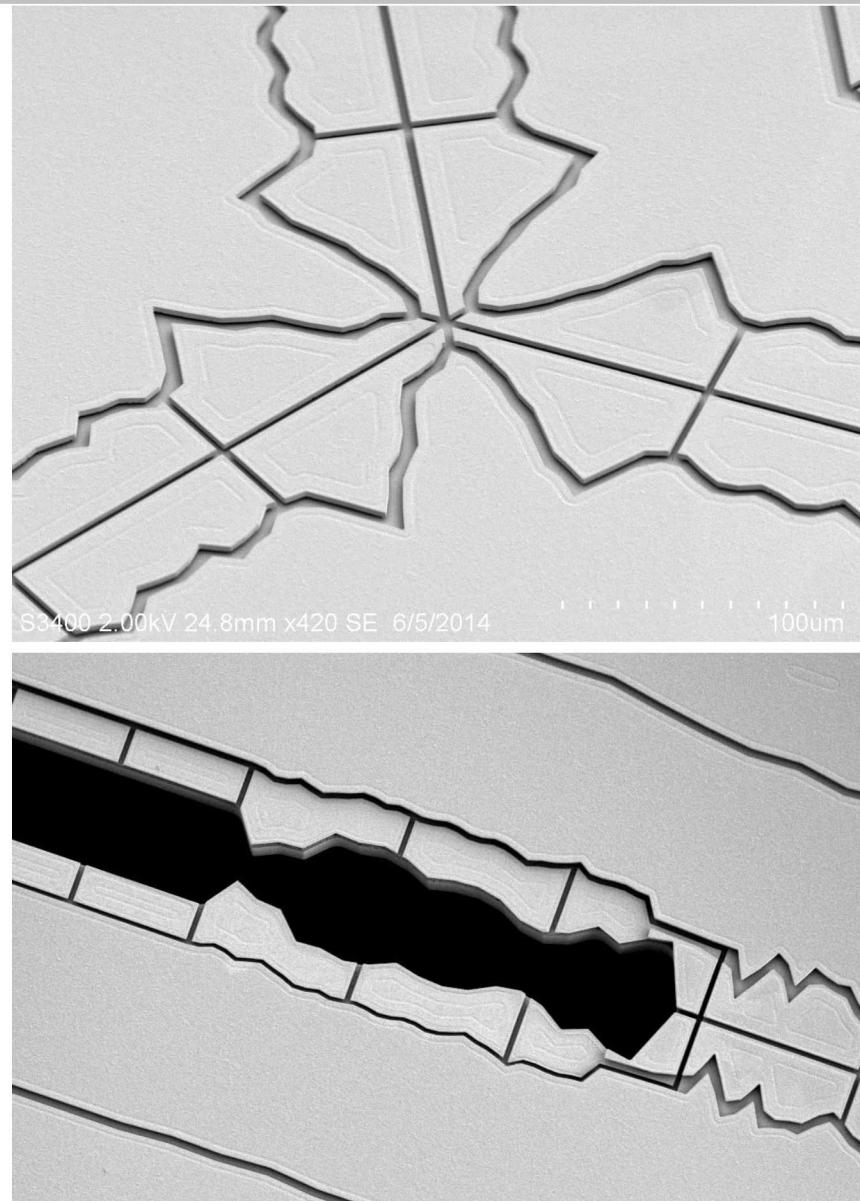
Primitives for scalable devices

Junctions enable 2-D scaling of ion traps

- Fabricated and demonstrated in multiple traps

Slotted trapping regions

- Optical access (NA 0.25)
Enables focus $2\mu\text{m}$ (@370nm)
- Transitions to above surface necessary to integrate junctions and scale traps
- Modulations reduce pseudopotential bumps to $<4\text{meV}$



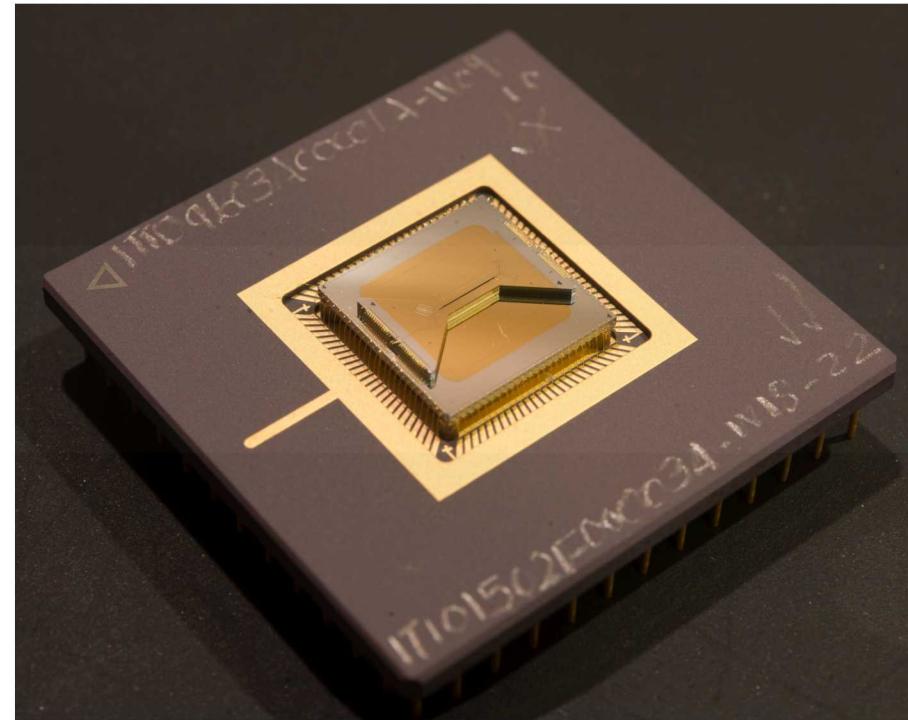
Device Packaging

Why have a packaging standard?

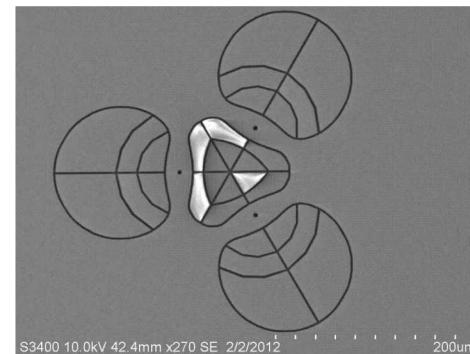
- Plug and trap package
 - Compatible with chambers of many groups
 - Standardized packaging and testing

Packaging developments

- Automatic wirebonding
 - Small pitch possible
 - Improved yield
- Electrical shorts and capacitance test
- Parametric verification (opens test)
- Known good trap
 - Easy deployment
 - Anyone who tried to trap succeeded



Parametric verification

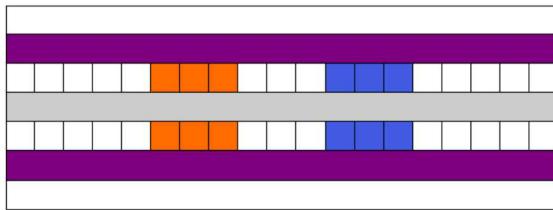


We deliver known good devices

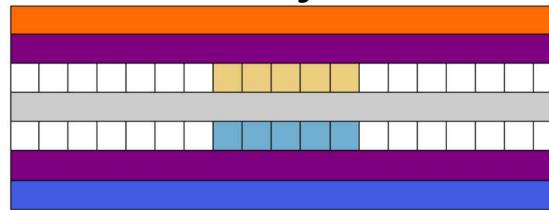
Shuttling in surface traps

- Remaining solutions compensate for micromotion → should produce no curvature

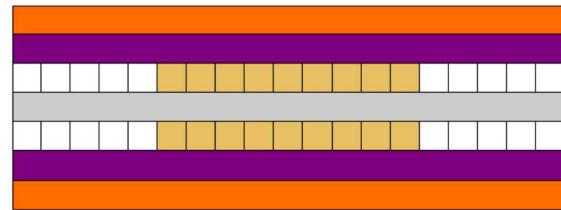
E_x



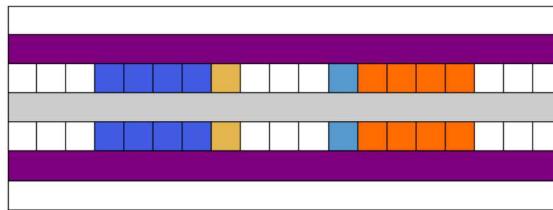
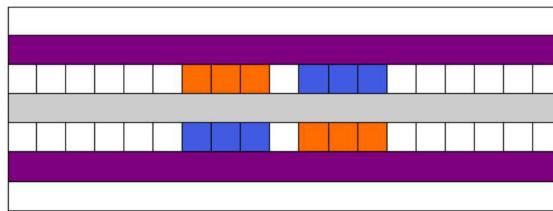
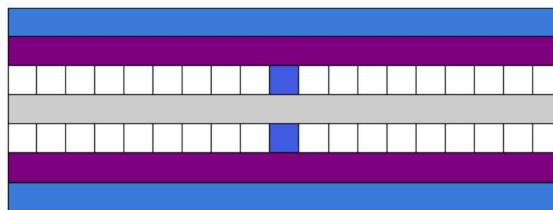
E_y



E_z



Symmetric

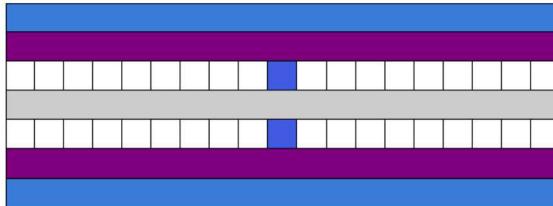


r.f.

Parametric Rotation Amplitudes

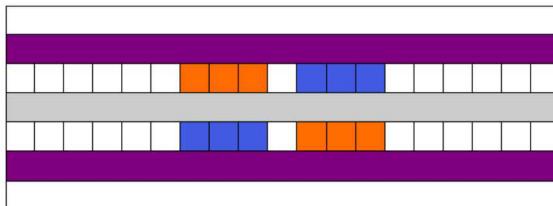
e_x, e_y, e_z : Eigenvalues

$\partial_{xx}\phi$



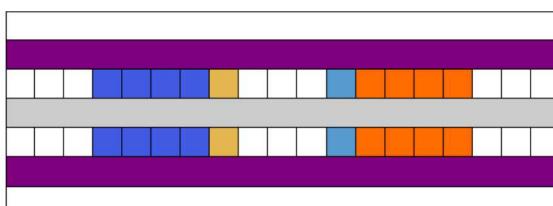
$$e_y \sin^2(\alpha) + e_x \cos^2(\alpha)$$

$\partial_{xy}\phi$



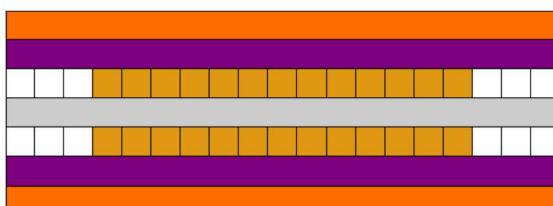
$$(e_y - e_x) \sin(\alpha) \cos(\alpha) \cos(\beta)$$

$\partial_{xz}\phi$



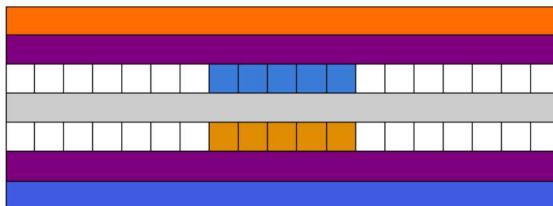
$$(e_x - e_y) \sin(\alpha) \cos(\alpha) \sin(\beta)$$

$\partial_{yy}\phi$



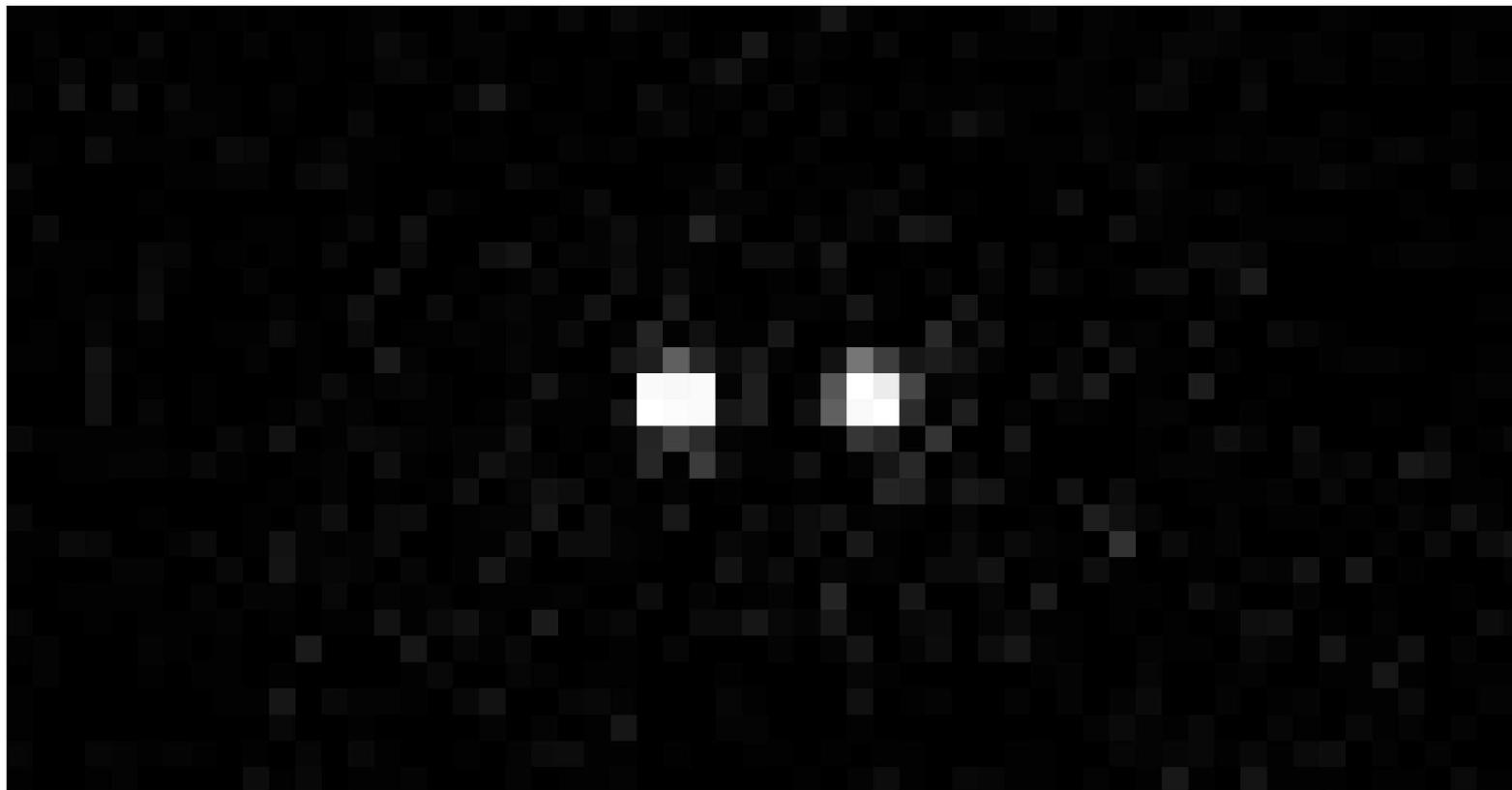
$$(\cos^2(\beta) - \sin^2(\beta)) (e_x \sin^2(\alpha) + e_y \cos^2(\alpha)) + e_z \sin^2(\beta) - e_z \cos^2(\beta)$$

$\partial_{yz}\phi$



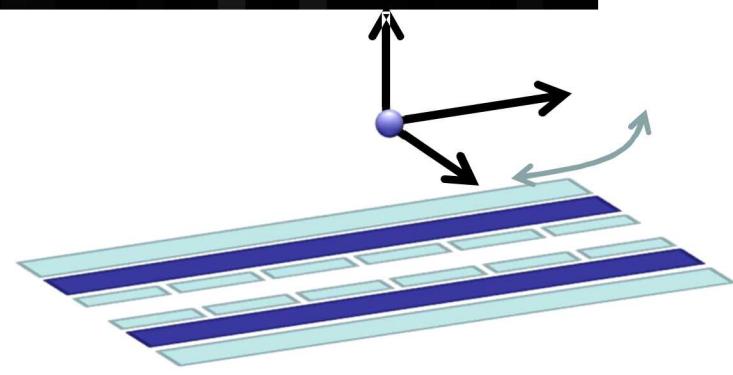
$$\sin(\beta) \cos(\beta) (-e_x \sin^2(\alpha) - e_y \cos^2(\alpha) + e_z)$$

Rotation of chains experimental realization



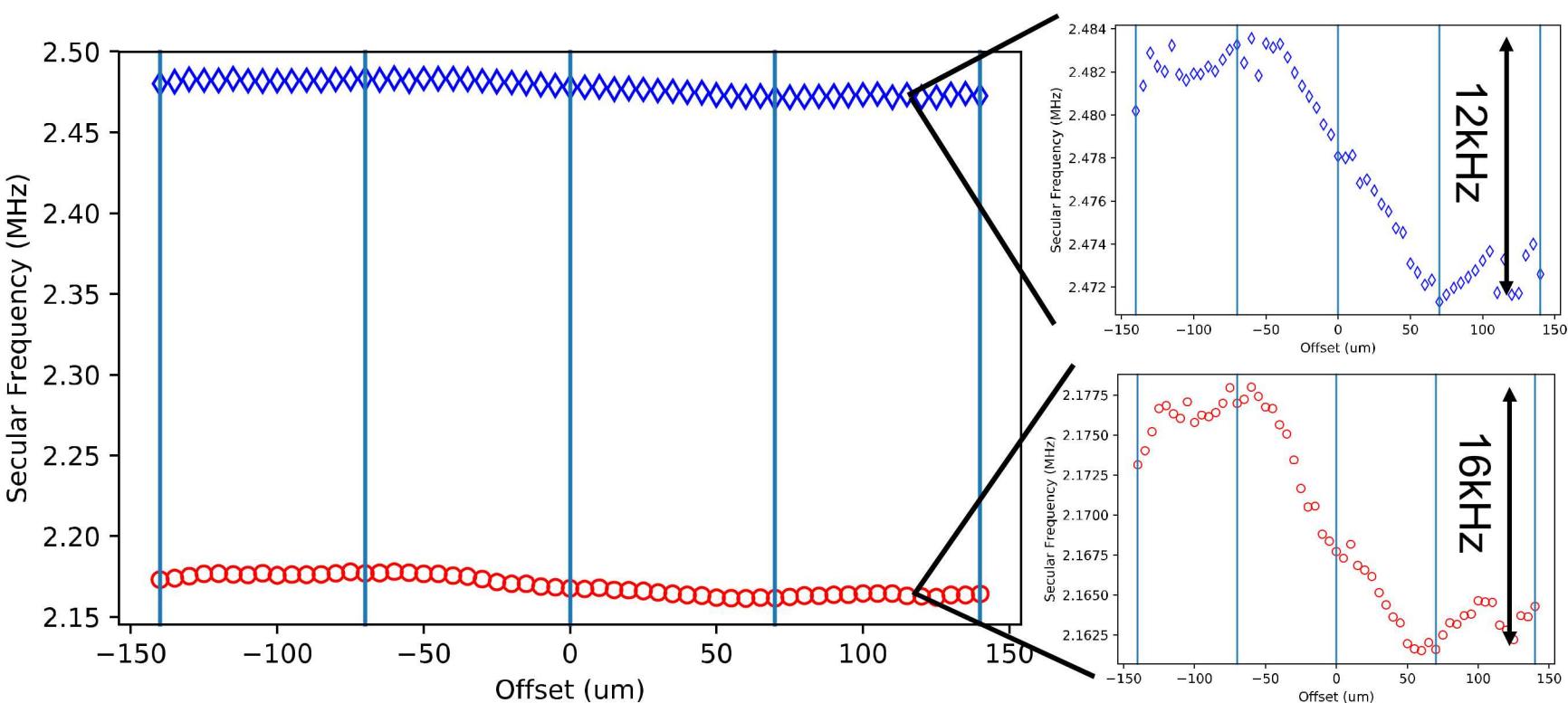
To be characterized as function of swapping time

- Swapping fidelity
- Accumulated motion



Trap frequency vs linear offset

- Trap frequencies are stable to within 16 kHz over the course of linear shuttling



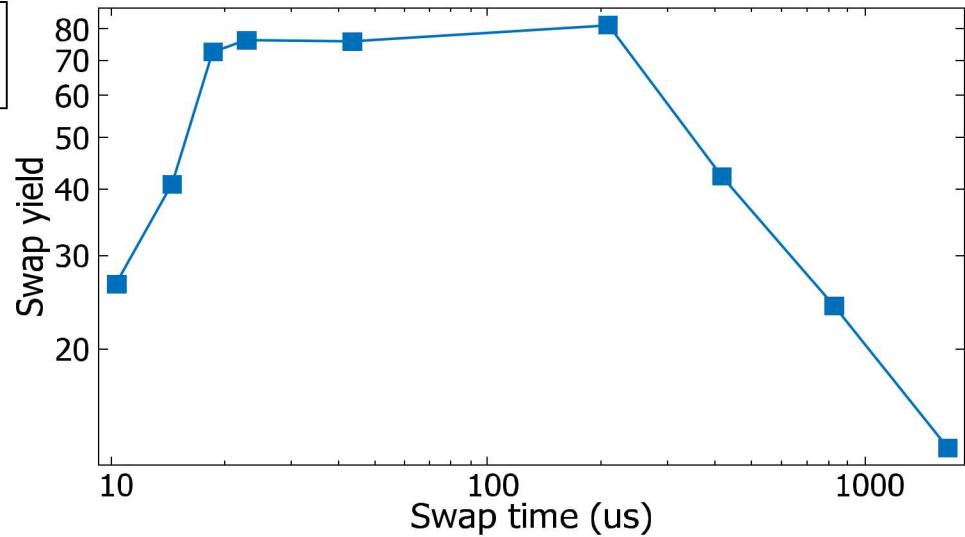
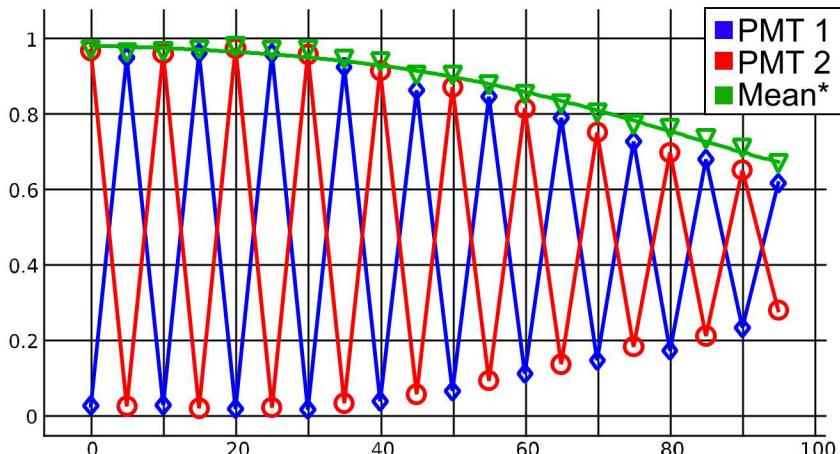
Conclusion

Sandia microfabricated surface traps are ready for your high fidelity operations

Demonstrated:

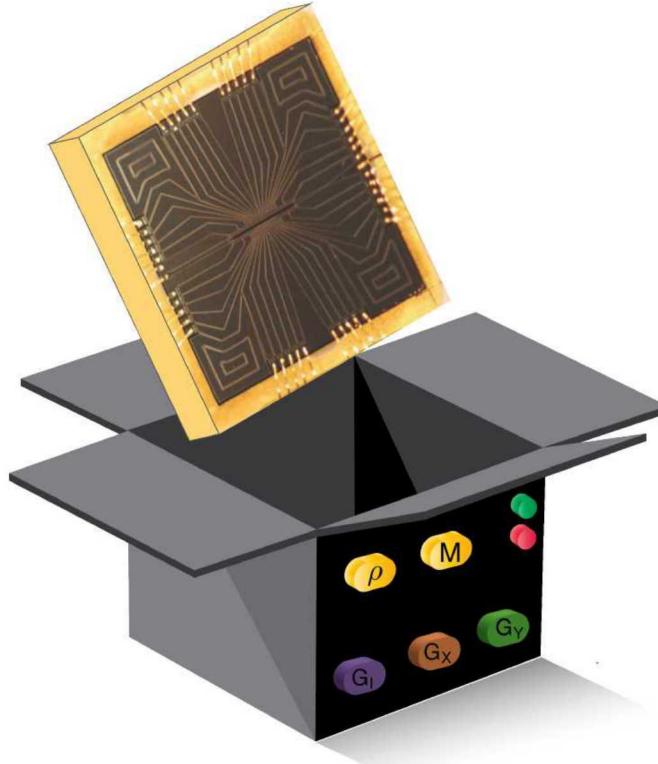
- Long lifetime, observed ion > 100h
- High fidelity microwave single qubit gates
Process infidelity $7.2(7) \times 10^{-5}$
below fault tolerance threshold $\frac{1}{2} \|\cdot\|_{\diamond} = 8(1) \times 10^{-5}$
- High fidelity Raman laser single qubit gates
Process infidelity 1.6×10^{-4} $\frac{1}{2} \|\cdot\|_{\diamond} = 5.3(2) \times 10^{-4}$
- High fidelity two qubit gates
Process infidelity $4.2(6) \times 10^{-3}$ $\frac{1}{2} \|\cdot\|_{\diamond} = 38(5) \times 10^{-3}$

Swapping fidelity



- Best fidelity between 20μs and 200μs
- Failure probability increases with number of swaps (heating)

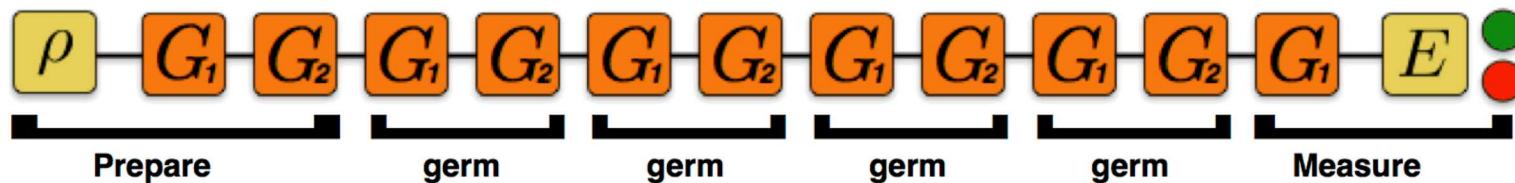
Gate Set Tomography



Developed at Sandia by
QCVV team

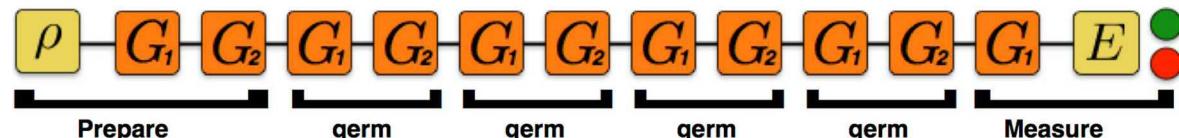
- No calibration required
- Detailed debug information
- Efficiently measures performance characterizing fault-tolerance (diamond norm)
- Detects non-Markovian noise

Uses structured sequences to amplify all possible errors



GST Experiments

Single qubit BB1 compensated microwave gates on $^{171}\text{Yb}^+$

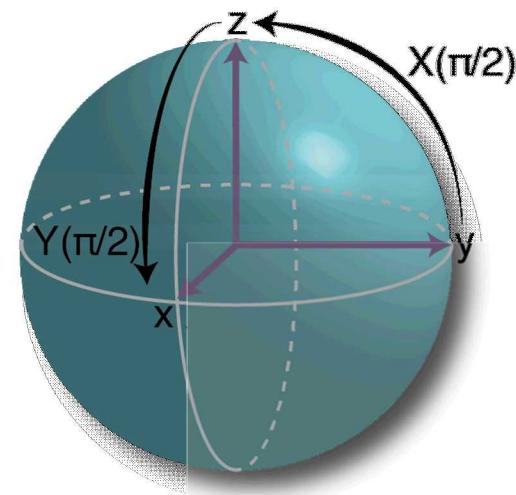


Desired “target” gates:

G_i Idle (Identity)

G_x $\pi/2$ rotation about x -axis

G_y $\pi/2$ rotation about y -axis



Fiducials:

{}

Gx

Gy

$$Gx \cdot Gx$$

$Gx \cdot Gx \cdot Gx$

Gy · Gy · Gy

Ge

Gi

$$Gx \cdot Gy$$

$$Gx \cdot Gy \cdot Gi$$

$$Gx \cdot Gi \cdot Gy$$

$Gx \cdot Gi \cdot Gi$

Gy · Gi · Gi

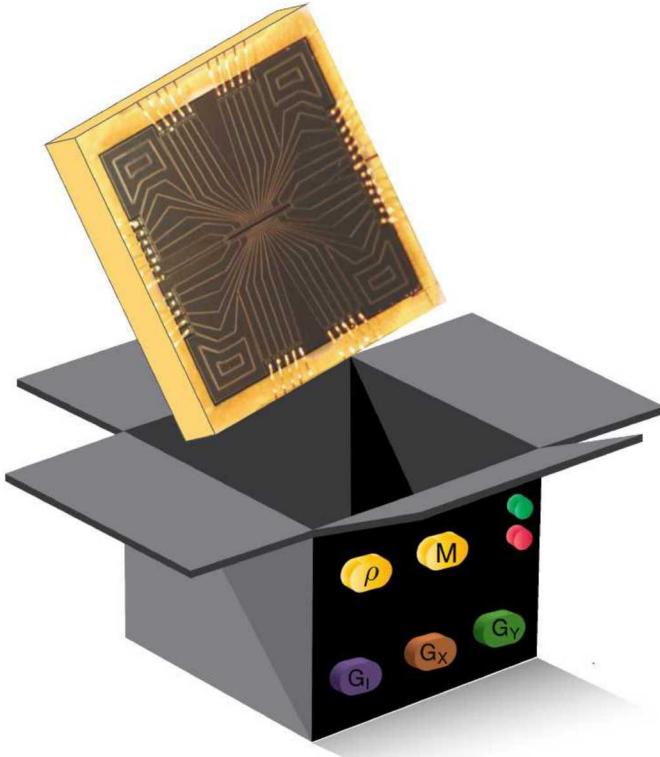
$$Gx \cdot Gx \cdot Gi \cdot Gy$$

$x \cdot Gx \cdot Gy \cdot Gx \cdot Gy \cdot Gy$

Approximately prepare 6 points on Bloch sphere

$Gx \cdot Gy \cdot Gy \cdot Gi$

Context and time dependency of gates



Assumptions:

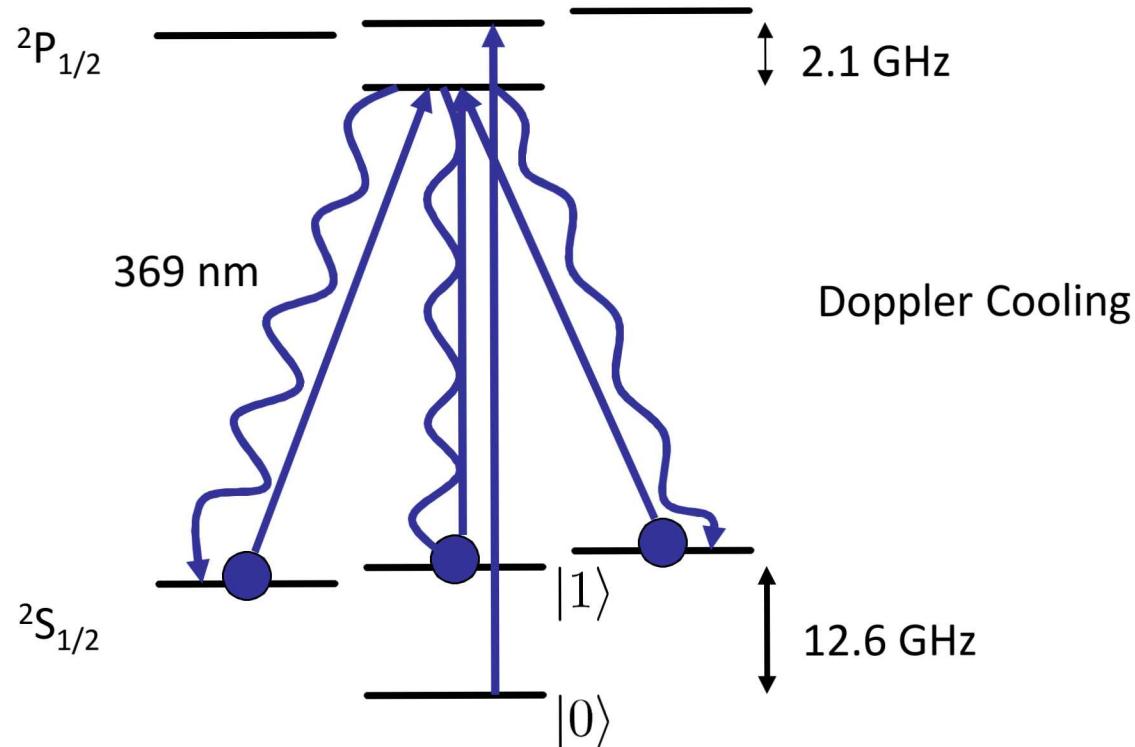
- Qubits in a box
- Pressing a button always executes the exactly same operation
- Independent from context (gates executed before)
- Independent from when a gate is executed

GST uses a large (over-complete) number of sequences.

We can look whether the assumptions are satisfied

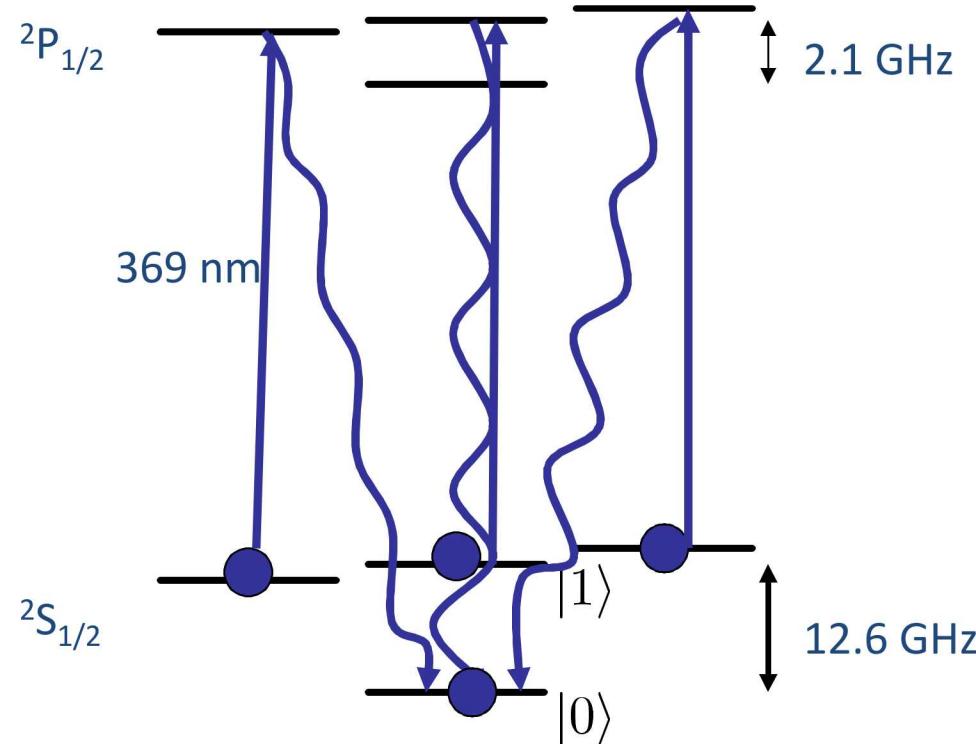
Ongoing work to improve and distinguish detection of context and time dependence of classical control

The Ytterbium Qubit



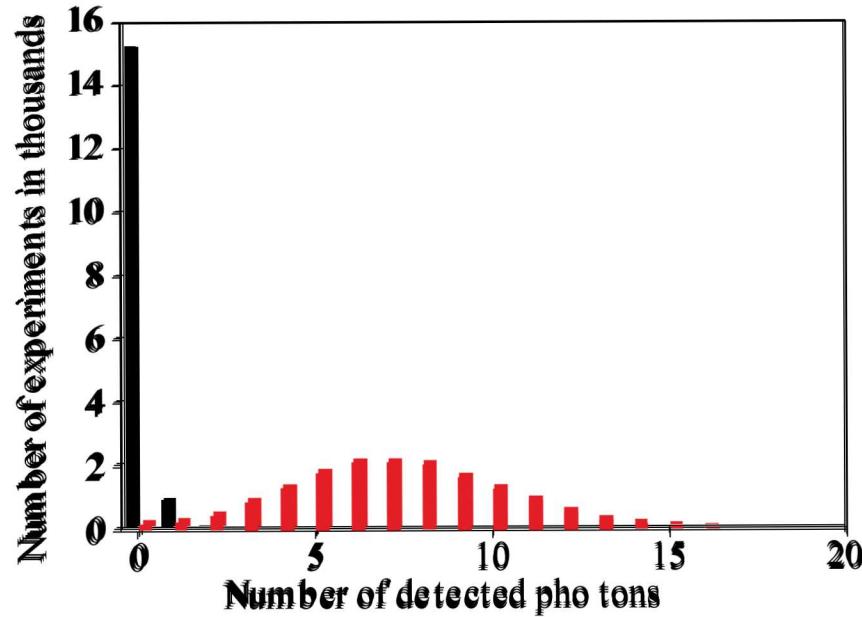
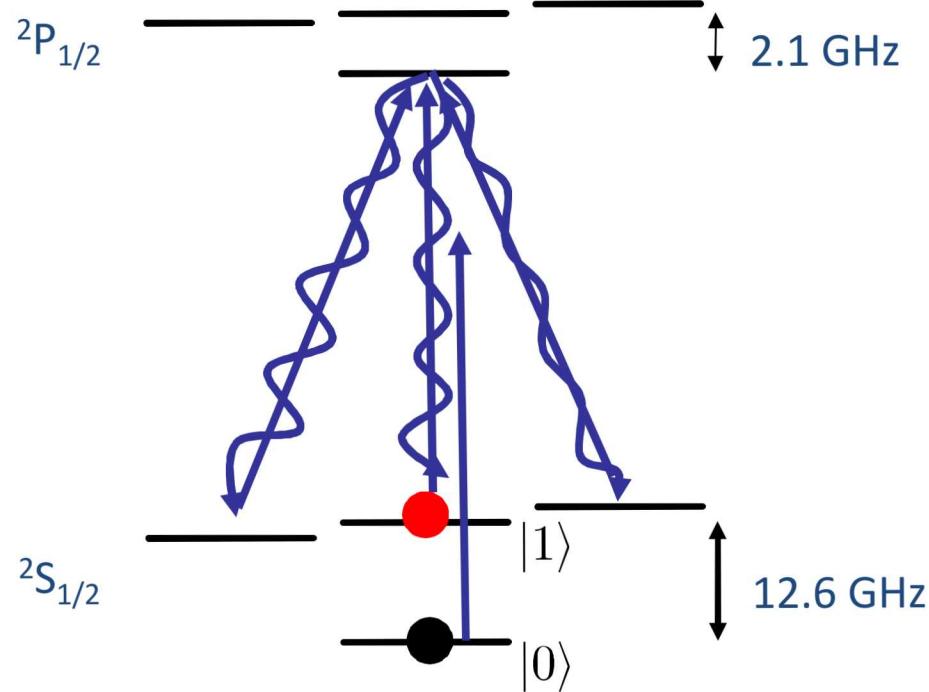
clock state qubit, magnetic field insensitive.

state initialization

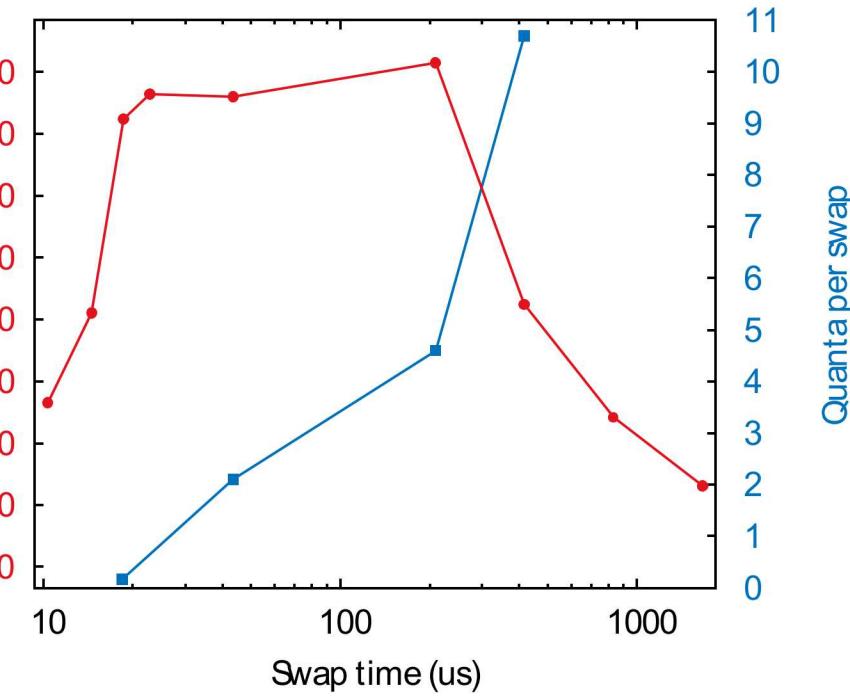
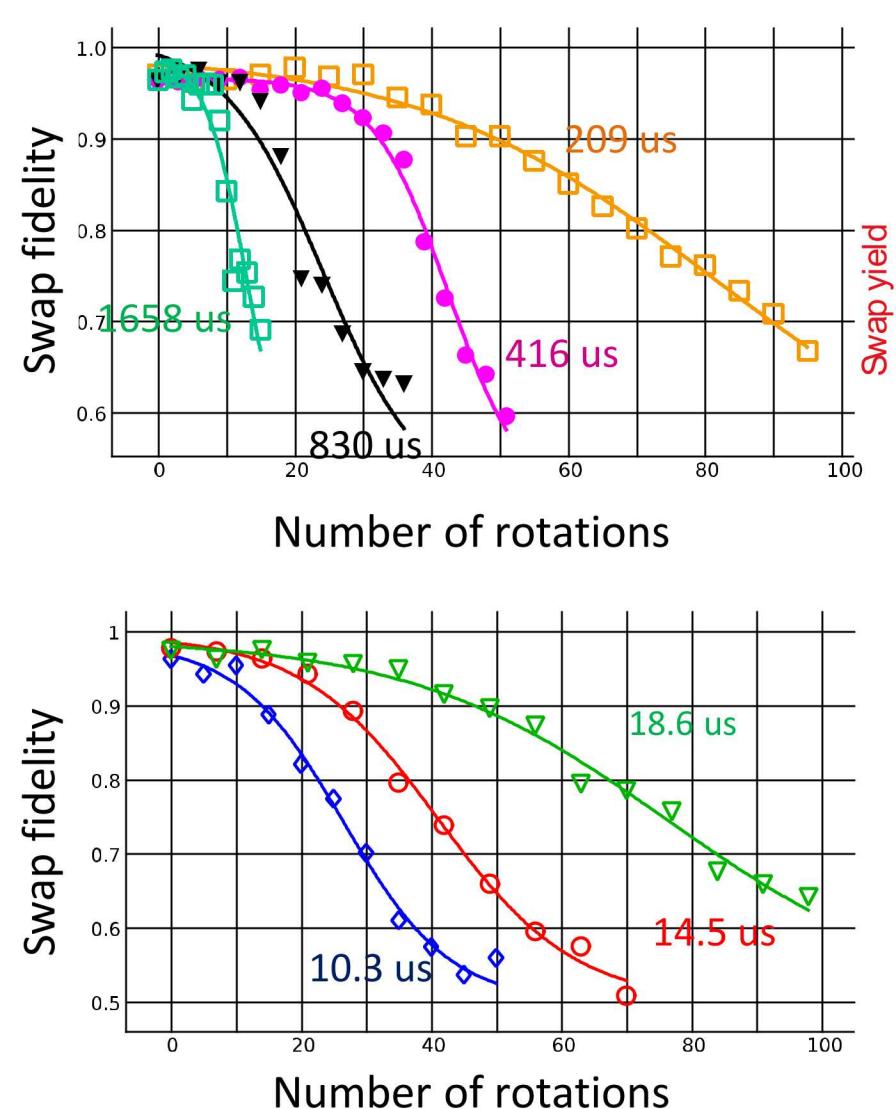


clock state qubit, magnetic field insensitive.

$^{171}\text{Yb}^+$ state detection



Swapping fidelity

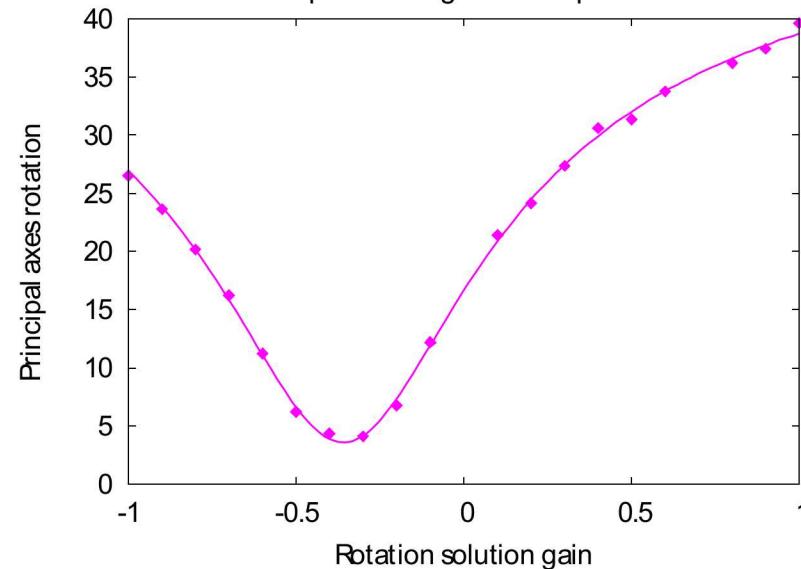
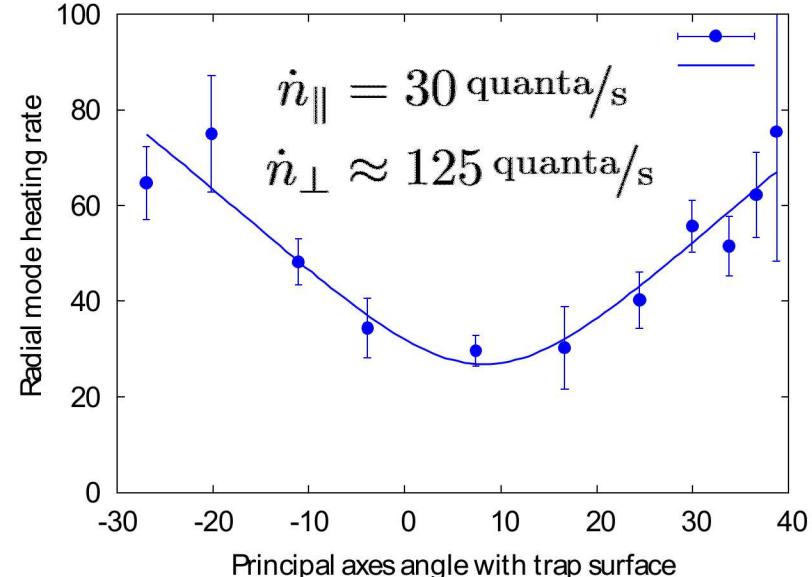


- Best fidelity between 20 μ s and 200 μ s
- Failure probability increases with number of swaps (heating)

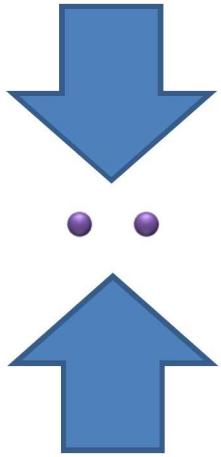
heating rates

Heating rates as function of principal axes rotation

- Principal axes rotation measured by measuring π -times of Rabi flopping on cooled motional modes
- Minimal heating rates for motional mode parallel to trap surface \dot{n}_{\parallel}
- Without technical noise: Vertical mode has at most $\dot{n}_{\perp} \leq 2\dot{n}_{\parallel}$
(P. Schindler, et al., Phys. Rev. A **92**, 013414 (2015).)
- Limited by technical noise

 $^{171}\text{Yb}^+$, Trap frequency 2.8 MHz, r.f. 50 MHz

Process fidelity of two-qubit gate



Currently:

- Two ions in single trap well
- No individual addressing
- Ideally all operations are symmetric
- Only symmetric subspace of two-qubit Hilbert space is accessible

Solution:

Perform GST on symmetric subspace
of two-qubit Hilbert space

Fundamental gates:

G_I

$$G_{XX} = G_X \otimes G_X$$

$$G_{YY} = G_Y \otimes G_Y$$

G_{MS}

9 Preparation Fiducials

12 Germs

6 Measurement Fiducials:

Linear chain melting



Slightly buckled chain stability



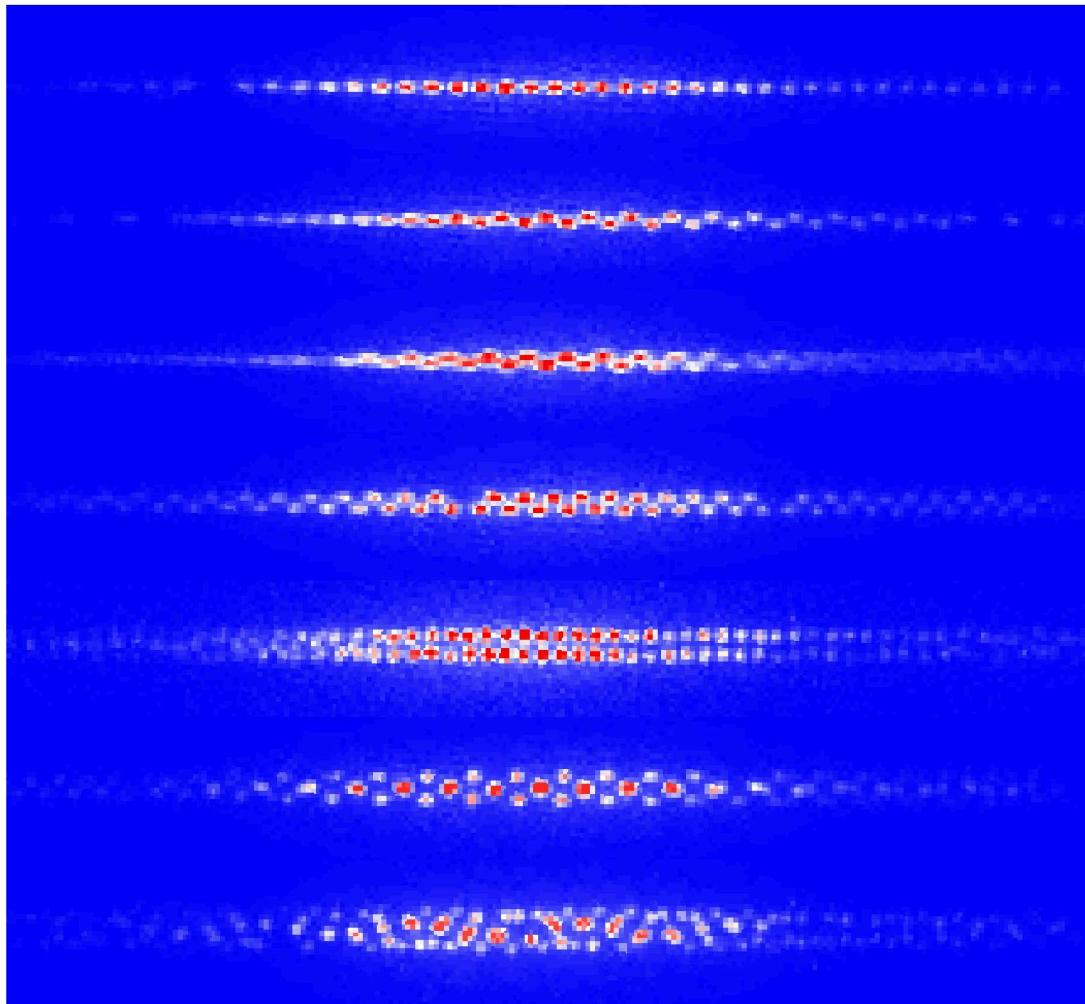
Ramping up buckling



Ion “braid” stability



Compression of ion chains



lifetime

15 min

1.5 hours



> 16 hours